

## SECURITIES AND EXCHANGE COMMISSION

WASHINGTON, D.C. 20549

Amendment No. 1 to

FORM 8-K

Dated April 21, 1999, as filed on April 26, 1999

CURRENT REPORT

PURSUANT TO SECTION 13 OR 15(d) OF  
THE SECURITIES EXCHANGE ACT OF 1934

April 21, 1999

-----  
Date of Report (Date of earliest event reported)

AMKOR TECHNOLOGY, INC.

-----  
(Exact name of Registrant as specified in its charter)

Delaware

-----  
(State or other jurisdiction of incorporation)

0-29472

-----  
(Commission File No.)

23-1722724

-----  
(IRS Employer Identification Number)1345 Enterprise Drive  
West Chester, PA 19380  
(610) 431-9600-----  
(Address of Principal Executive Offices)-----  
(Former name or former address, if changed since last report)

## Item 2. ACQUISITION OR DISPOSITION OF ASSETS

We have acquired the assets, excluding cash and cash equivalents, notes and accounts receivables, intercompany accounts and existing claims against third parties, of the Kwangju packaging and test facility, known as K4, of Anam Semiconductor, Inc. (the "Acquisition"). The purchase price for K4 was \$575.0 million, plus the assumption of up to \$7.0 million of employee benefit liabilities. We used debt financing to pay the purchase price for K4. We consummated the Acquisition on May 17, 1999. The asset purchase agreement for the Acquisition is exhibit 2.1 to this report, and an amendment to this agreement is exhibit 2.2 to this report. A press release issued by the Company in connection with the consummation of the Acquisition is exhibit 99.1 to this report.

Located in Kwangju, Korea, K4 is situated on approximately 100 acres and currently consists of a 1,000,000 square foot facility, including 782,000 square feet of manufacturing and administrative space. Opened in 1996, K4 has been ramping up production throughout 1997 and 1998 and provides packaging and test services for many of our most advanced packages. In addition, the K4 site has the infrastructure in place to accommodate four pre-configured modules for a total of 1.6 million square feet of incremental capacity.

In connection with the Acquisition, we entered into a Transition Services Agreement with ASI. Pursuant to this agreement, ASI will continue to provide many of the same services at K4 that it had provided prior to the Acquisition, including human resources, accounting and general administrative services and customer services. A copy of this agreement is attached hereto as Exhibit 10.2.

We also entered into an Intellectual Property License Agreement with ASI that became effective upon the closing of the Acquisition. Pursuant to this agreement, ASI transferred certain patents to us and licensed certain intellectual property rights to us under an exclusive, fully paid, perpetual license. We licensed these patents and other rights back to ASI on a non-exclusive basis. A copy of this agreement is attached hereto as Exhibit 10.1.

In connection with the Acquisition, we formed a special committee of our Board of Directors consisting of the five non-employee members of our Board of Directors. This special committee had the authority to review and approve the Acquisition. In connection with the Acquisition, the special committee hired financial and legal advisors. This special committee received a fairness opinion from its financial advisor and approved the Acquisition.

To finance the purchase price of K4, on May 6, 1999, we completed a private placement of \$425 million of senior notes and \$200 million of senior subordinated notes. The senior notes mature in May 2006 and have a coupon rate of 9.25%. The senior subordinated notes mature in May 2009 and have a coupon rate of 10.50%. We must pay interest semi-annually in May and November for all of the notes.

#### RELATIONSHIP WITH ASI

WHO IS ANAM SEMICONDUCTOR, INC.?

ASI is a Korean company engaged primarily in providing semiconductor packaging and test services. ASI currently operates four semiconductor packaging and test factories in Korea, including K4. ASI also operates a semiconductor wafer foundry in Korea. ASI derives substantially all of its revenues from the sale of its packaging and test services to us. ASI also derives all of its wafer fabrication revenues from the sale of services to us.

We have a long-standing relationship with ASI. ASI was founded in 1956 by Mr. H. S. Kim, the father of Mr. James Kim, our Chairman and Chief Executive Officer. Since January 1992, in addition to his other responsibilities, Mr. James Kim has served as Chairman and a Director of ASI. For the years ended December 31, 1996, 1997 and 1998, we derived 72%, 68% and 69% of our net revenues and 51%, 42% and 49% of our gross profit from sales of services performed for us by ASI.

In January 1998, we entered into new supply agreements with ASI. Under these agreements, we retain a first right to substantially all of its packaging and test services and the exclusive right to all of the output of its semiconductor wafer foundry. We expect to continue to purchase substantially all of ASI's packaging and test services and to purchase all of ASI's semiconductor wafer output.

## THE KOREAN FINANCIAL CRISIS

ASI has been severely affected by the economic crisis in Korea. In late 1997, Korea began to undergo a foreign currency liquidity crisis resulting in significant adverse economic circumstances and significant depreciation in the value of the won against the U.S. dollar. In order to address this situation, the government of Korea sought assistance from the International Monetary Fund and implemented a comprehensive policy intended to address the structural weaknesses in the Korean economy and financial sector. While the reform policies were intended to alleviate the economic difficulties and improve the economy over time, in the short term, they have resulted in: (1) slower economic growth, (2) a reduction in the availability of credit, (3) an increase in interest rates, (4) an increase in taxes, (5) an increase in the rate of inflation, (6) volatility in the value of the won, (7) an increase in the number of bankruptcies of Korean corporate entities and (8) unrest resulting from a significant increase in unemployment. Although the Korean economy recovered somewhat in the latter half of 1998, these conditions and similar conditions in other countries in the Asia Pacific region continue to pose a threat to the economies of such countries and to the region as a whole.

ASI historically operated with a significant amount of debt relative to its equity. The economic crisis in Korea led to sharply higher interest rates and significantly reduced opportunities for refinancing maturing debts. Because ASI maintained a substantial amount of short-term debt, its inability to refinance this debt created a liquidity crisis for ASI. In addition to its own leveraged financial position, ASI guarantees certain debt obligations of its affiliates, many of which have encountered financial difficulties as a result of the crisis.

### ASI WORKOUT

In October 1998, ASI announced that it had applied for and was accepted into the Korean financial restructuring program known as the "Workout." The Workout program is the result of an accord among Korean financial institutions to assist in the restructuring of Korean businesses and does not involve the judicial system.

We expect the Workout to significantly improve the financial condition of ASI. The Workout became effective in April 1999. The information setting forth the details of the Workout is based on the exchange rate

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of W1,207.8 to \$1.00 that was in effect as of December 31, 1998. The Workout contains the following provisions:

- o The creditor financial institutions will allow ASI to defer repayment on principal of ordinary loans until December 31, 2003. After December 31, 2003, ordinary loans with repayment terms will be payable through readjustment of repayment schedules in effect on October 24, 1998. For ordinary loans without repayment terms, the schedule to repay principal amounts will be determined by ASI and the creditor financial institutions at the end of such period.
- o The creditor financial institutions will allow ASI to defer repayment of principal under capital leases until December 31, 1999, with payments of principal to resume under a seven-year installment plan thereafter.
- o The creditor financial institutions will allow ASI to defer the maturity of its won-denominated debentures for an additional three-year term after currently scheduled maturity dates.
- o The creditor financial institutions will allow ASI to make no interest payments on ordinary loans until December 31, 1999. The creditor financial institutions will add accrued interest to the principal amounts of these loans every three months.

- o The creditor financial institutions will reduce interest rates on ASI's remaining outstanding won-denominated ordinary loans to 10% or the prime rate of each creditor financial institution, whichever is greater. This would reduce ASI's weighted average interest rate from 12.9% before the Workout to 10.5% after the Workout.
- o The creditor financial institutions will give ASI a grace period until December 31, 2003 against enforcement of guarantees made by ASI for liabilities of ASI's affiliates. In addition, interest will not accrue on guaranteed obligations during this period.
- o The creditor financial institutions will provide to ASI a short-term loan of W50 billion (\$41 million) at the prime rate plus 1%, to be repaid with proceeds from the sale of K4.
- o The creditor financial institutions may receive additional payments if ASI's financial performance exceeds expectations.
- o For the duration of the Workout, the creditor financial institutions will be entitled to vote the ASI shares owned by Mr. James Kim and his family.
- o The creditor financial institutions will convert W250 billion (\$208 million) of ASI debt held by the creditor financial institutions into: (1) equity shares of ASI in the amount of W122.3 billion (\$102 million), (2) five-year non-interest bearing convertible debt in the amount of W108.1 billion (\$90 million) and (3) non-interest bearing loans in the amount of W19.6 billion (\$16 million), provided that we make a \$150 million equity investment in ASI. The conversion would take place in installments over four years, with the first installment to be made in October 1999, at a conversion rate equal to W5,000 per share, the par value of ASI's common stock. In order for the initial conversion of debt to take place in accordance with the terms of the Workout, ASI will have to undergo a series of corporate actions, including a reverse stock split, to bring the fair market value of its equity shares to a price at least equal to the par value of such shares. The conversion of ASI debt by the creditor financial institutions would coincide with each installment of our equity investment in ASI.

We have executed a letter with ASI committing to make the equity investment in installments of \$41 million in each of 1999, 2000 and 2001 and \$27 million in 2002. Our commitment to invest in ASI is subject to: (1) execution of a definitive stock purchase agreement, (2) concurrent conversion of debt by the creditor financial institutions, (3) the Workout remaining in effect and (4) the supply agreements between our company and ASI remaining in effect. We would purchase the ASI shares at W5,000 per share. Because our commitment is in U.S. dollars, the number of shares we would purchase will vary based on the exchange rate of Korean won to U.S. dollars.

Upon completion of the first installment of our equity investment in ASI and conversion of debt by the creditor financial institutions, we expect the relative equity ownership of ASI among the creditor financial institutions, the Kim family and our company to be approximately 27%, 21% and 21%, respectively, subject to the creditor financial institutions' right to vote the Kim family's stock for the duration of the Workout. Upon completion of all conversions of debt by the creditor financial institutions and all installments of our equity investment pursuant to the Workout, we expect the relative equity ownership of ASI among the creditor financial institutions, the Kim family and our company to be approximately 29%, 11% and 43%, respectively, subject to the creditor financial institutions' voting rights. Upon conversion of all of the convertible debt issued to the creditor financial institutions, which would be permitted beginning one year after the date of issuance of such debt, the ownership of ASI among the creditor financial institutions, the Kim family and our company would be approximately 43%, 9% and 34%, respectively, subject to the creditor financial institutions' voting rights.

The creditor financial institutions have the right to terminate or modify the Workout if ASI does not fulfill the terms of the Workout, including meeting certain financial targets. In addition, the creditor financial institutions can modify the terms of the Workout upon agreement of creditor financial institutions holding at least 75% of the debt restructured under the Workout. If the creditor financial institutions subsequently terminate the Workout, the creditor financial institutions could reinstate and enforce the original terms of ASI's debt, including accelerating ASI's obligations and pursuing ASI's guarantees of its affiliates' debt. If this were to occur, ASI's and our businesses would be harmed.

#### RELATIONSHIP WITH ASI FOLLOWING THE WORKOUT AND THE ACQUISITION OF K4

We expect ASI to continue to be important to our business in the future. Under our supply agreements with ASI, we have a first right to substantially all of the packaging and test services of ASI and the exclusive right to all of the wafer output of ASI's wafer foundry. The supply agreements have a five-year term, expiring December 31, 2002, and may be terminated by either party upon five years' written notice after completion of the initial five year term. The supply agreements may also be terminated upon breach or insolvency of either party. We expect to continue to have certain contractual and other business relationships with ASI, including those under the supply agreements. The supply agreements generally provide for continued cooperation between our company and ASI in research and development, as well as cross-licensing of intellectual property rights. The supply agreements also provide for continued capital investment by ASI based on our forecasts. It is not certain whether the Workout will be sufficient to enable ASI to continue to provide services to our company at current levels or to obtain funds for capital expansion.

As described above, concurrent with the completion of the Acquisition, we entered into a transition services agreement and an intellectual property licensing agreement with ASI.

Our company and ASI will also continue to have close ties due to our overlapping ownership and management. We expect that Mr. James Kim will continue to serve as Chairman of ASI and as our Chairman and Chief Executive Officer. The Kim family currently beneficially owns approximately 65.8% of our outstanding common stock and approximately 40.7% of ASI's common stock. Both our investment in ASI and the conversion of debt to equity will substantially decrease the Kim Family's ownership in ASI. Furthermore, for the duration of the Workout, the creditor financial institutions will be entitled to vote the ASI shares owned by Mr. James Kim and his family. Even though the Kim family's ownership of ASI will be reduced and the voting rights in their ASI shares assigned to the creditor financial institutions, we believe that the Kim family will continue to exercise significant influence over our company, ASI and its affiliates.

We have also entered into agreements with ASI and Texas Instruments, Inc. relating to our wafer fabrication business. In addition, we may engage in other transactions with ASI from time to time that are material to us. To provide you with additional information about our relationship with ASI, we hereby incorporate by reference to our Annual Report on Form 10-K filed on March 31, 1999 Part III, Item 13, "Certain Relationships and Related Transactions," into this Report.

The indentures entered into in connection with our financing of the acquisition of K4 (Exhibits 4.1 and 4.2 to this Report) restrict our ability to enter into transactions with ASI and other affiliates.

#### ASI CONSOLIDATED CONDENSED FINANCIAL INFORMATION

The following is a summary of the audited consolidated financial information pertaining to ASI. The financial information is prepared in accordance with Korean GAAP, which differs significantly from U.S. GAAP. U.S. GAAP financial statements are not available.

	YEAR ENDED DECEMBER 31,	
	1997	1998
	(IN MILLIONS)	
INCOME STATEMENT DATA:		
Sales.....	W1,786,457	W2,547,326
Gross profit.....	279,186	201,926
Operating income.....	176,028	77,734
Interest expense, net.....	113,066	313,971
Foreign exchange (gains) losses, net, loss from forward contract and amortization of deferred charges.....	345,232	(182,958)
(Gains) from sale of investments.....	(3,473)	(89,397)
Loss on valuation of inventories.....	724	24,150
Other, net.....	12,192	11,041
Total non-operating (income) expense, net.....	467,741	76,807
Ordinary income (loss) before income taxes and extraordinary items.....	(291,713)	927
Income tax.....	7,922	2,063
Extraordinary losses, net.....	1,039	193,571
Minority interests.....	(1,206)	(72,049)
Equity in losses of affiliates.....	49,261	18,830
Net loss.....	W (348,729)	W (141,488)
OTHER FINANCIAL DATA:		
Depreciation expense.....	W 137,989	W 311,461

	DECEMBER 31	
	1997	1998
	(IN MILLIONS)	
BALANCE SHEET DATA (AT END OF PERIOD):		
ASSETS		
Cash and bank deposits.....	W 215,024	W 37,969
Trade accounts and notes receivable, net.....	189,522	144,501
Inventories.....	260,302	183,786
Short-term loans to affiliates.....	62,846	188,188
Other current assets.....	179,119	95,921
	-----	-----
Total current assets.....	906,813	650,365
	-----	-----
Property, plant and equipment, net.....	2,159,466	2,284,263
Investments.....	121,880	72,136
Long-term trade accounts receivable.....	203,739	18,876
Other long-term assets.....	544,132	276,656
	-----	-----
Total long-term assets.....	3,029,217	2,651,931
	-----	-----
Total assets.....	W3,936,030	W3,302,296
	=====	=====
LIABILITIES AND SHAREHOLDERS' EQUITY		
Short-term borrowings.....	W1,720,916	W1,351,919
Current maturities of long-term debt.....	120,913	249,526
Provision for loss contingencies related to affiliate companies.....	--	190,000
Other current liabilities.....	282,653	270,895
	-----	-----
Total current liabilities.....	2,124,482	2,062,340
	-----	-----
Long-term debt, net of current maturities.....	736,784	494,867
Long-term obligations under capital leases.....	861,813	661,286
Other long-term liabilities.....	111,017	112,938
	-----	-----
Total long-term liabilities.....	1,709,614	1,269,091

Total liabilities.....	3,834,096	3,331,431
Minority interests in consolidated subsidiaries.....	25,160	21,538
Shareholders' equity(deficit).....	76,774	(50,673)
Total liabilities and shareholders' equity (deficit)....	W3,936,030	W3,302,296

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Beginning in late 1997 and continuing into 1998, Korea experienced severe economic instability as well as devaluation of the Korean won relative to the U.S. dollar. The exchange rate as of December 31, 1996, was W884 to \$1.00 as compared to W1,415 to \$1.00 as of December 31, 1997 and W1,207 to \$1.00 as of December 31, 1998. No representation is made that the won or U.S. dollar amounts referred to herein could have been or could be converted into U.S. dollars or won, as the case may be, at any particular rate or at all.

A significant amount of the current and long-term liabilities of ASI are denominated in U.S. dollars and other foreign currencies. At December 31, 1998, the amount of U.S. dollar and other foreign currency denominated short-term borrowings, current maturities of long-term debt, long-term debt (net of current maturities) and capital lease obligations were W436 billion, W35 billion, W103 billion and W686 billion, respectively. A substantial amount of ASI's revenues are denominated in U.S. dollars which mitigates ASI's exposure to currency fluctuations.

As of December 31, 1998, ASI was contingently liable under guarantees in respect of debt of ASI's affiliates in the Anam Group in the aggregate amount of approximately W455 billion. If any affiliates of ASI were to fail to make interest or principal payments or otherwise default under their debt obligations then, pursuant to the Workout, creditors could not seek to enforce the guarantees provided by ASI until December 31, 2003.

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#### Item 7. FINANCIAL STATEMENTS AND EXHIBITS.

The following financial statements and exhibits are filed as part of this Report:

(a) Financial statements of K4 for the year ended December 31, 1998 were previously filed with this report on April 26, 1999.

(b) Pro forma financial information for the year ended December 31, 1998 was previously filed with this report on April 26, 1999.

(c) Exhibits in accordance with Item 601 of Regulation S-K:

EXHIBIT NUMBER	DESCRIPTION
2.1	Asset Purchase Agreement by and between Amkor Technology Inc. and Anam Semiconductor Inc., dated December 30, 1998.*
2.2	Amendment to Asset Purchase Agreement by and between Amkor Technology Inc. and Anam Semiconductor Inc.
4.1	Indenture dated as of May 13, 1999 and form of Senior Note.**
4.2	Indenture dated as of May 13, 1999 and form of Senior Subordinated Note.**

- 10.1 Intellectual Property Transfer and License Agreement by and between Amkor Technology Inc. and Anam Semiconductor Inc.
- 10.2 Transition Services Agreement by and between Amkor Technology Inc. and Anam Semiconductor Inc.
- 23.1 Consent of Samil Accounting Corporation.
- 99.1 Press release dated April 21, 1999.\*\*\*
- 99.2 Press release dated May 17, 1999.

- - - - -  
\* Incorporated by reference to the Company's Annual Report on Form 10-K filed March 31, 1999.

\*\* Incorporated by reference to the Company's quarterly Report on Form 10-Q filed May 17, 1999.

\*\*\* Previously filed with this report.

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#### SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

AMKOR TECHNOLOGY, INC.

By: /s/ Frank J. Marcucci

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Frank J. Marcucci  
Chief Financial Officer

Dated: June 1, 1999

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SECURITIES AND EXCHANGE COMMISSION  
Washington, D.C. 20549

EXHIBITS

TO

FORM 8-K

CURRENT REPORT PURSUANT TO SECTION 13 OR 15(d)  
OF



THE SECURITIES EXCHANGE ACT OF 1934

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AMKOR TECHNOLOGY, INC.  
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INDEX TO EXHIBITS

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\*\*\* Previously filed with this report.

[EXECUTION COPY]

AMENDMENT  
TO  
ASSET PURCHASE AGREEMENT

BY AND BETWEEN

AMKOR TECHNOLOGY, INC.

as Purchaser

AND

ANAM SEMICONDUCTOR, INC.

as Seller

Dated as of May 6, 1999

## AMENDMENT TO ASSET PURCHASE AGREEMENT

This is AMENDMENT TO ASSET PURCHASE AGREEMENT (the "Amendment"), dated May 6, 1999 by and between Amkor Technology, Inc., a corporation organized under the laws of the State of Delaware of the United States, ("Amkor" or "Purchaser") and Anam Semiconductor, Inc., a corporation organized under the laws of the Republic of Korea ("Seller"). Purchaser and Seller shall sometimes each be referred to as a Party and collectively as the Parties.

## RECITALS:

WHEREAS, Seller and Purchaser entered into an Asset Purchase Agreement dated December 30, 1998 (the "Original Agreement") under which Seller agreed to sell and Purchaser agreed to purchase the semiconductor packaging and test operations generally known as K4 located at Advanced Science & Industrial Complex, 2 block, Daechon-dong, Buk-gu, City of Kwangju 500-470 the Republic of Korea ("Business");

WHEREAS, it is Seller's intention that it will use the proceeds from the sale of K4, upon Closing, primarily for the repayment of its debt to its Korean creditors, including certain banks and other forms of financial institutions in Korea (the "Workout Banks"); and

WHEREAS, both Parties desires to make changes to certain sections of the Original Agreement by entering in an amendment in accordance with Section 5.7 of the Original Agreement.

NOW THEREFORE, in consideration of the mutual agreements, covenants, representations and warranties contained herein, and in reliance thereon, Purchaser and Seller hereby agree as follows:

#### DEFINITIONS:

Unless specifically defined otherwise herein, the terms defined herein shall have the same meanings as they were used in the Original Agreement.

#### AMENDMENTS OF CERTAIN DEFINITIONS

The definition of "IP Licensing Agreements" in the Original Agreement (on page 4 of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

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"IP Assignment and Licensing Agreements" have the meaning as described in the paragraph immediately following Section 1.1(h) of this Amendment.

The definition of "Base Rate" in the Original Agreement (on page 2 of the Original Agreement) is hereby deleted.

#### 1.1. Amendment of Section 1.1. "Sale and Purchase of Assets" of the Original Agreement.

The paragraph immediately following Section 1.1(h) of the Original Agreement (on page 9 of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

"The Parties agree that certain Intellectual Properties (including Licensed Intellectual Property) which are identified in Schedule 2.16 as the Assigned Intellectual Property shall be assigned to Purchaser hereunder, while the Intellectual Properties which are identified in Schedule 2.16 as the Licensed Intellectual Properties shall be licensed to Purchaser rather than being assigned to Purchaser. With respect to the Assigned Intellectual Properties, to the extent legally and/or contractually permissible, Seller shall sell, transfer, convey and assign to Purchaser, free and clear of all Liens of every kind, nature and description, all right, title and interest of Seller in and to such Intellectual Properties. Immediately after the assignment of the Assigned Intellectual Properties, however, Purchaser shall grant to Seller, an irrevocable, worldwide, non-exclusive, perpetual, paid-up, royalty-free and transferable (and sub-licensable) license (or sub-license) to utilize such Assigned Intellectual Properties (including the Licensed Intellectual Property), after obtaining any and all consents necessary therefor for Seller to be able to operate the other businesses of Seller substantially in the manner as such businesses were operated by Seller. With respect to the Licensed Intellectual Properties, to the extent legally and/or contractually permissible, Seller hereby shall grant to Purchaser and its Affiliates, effective at the Closing Date, an irrevocable, worldwide, non-exclusive, perpetual, paid-up, royalty-free and transferable (and sub-licensable) license (or sub-license) to utilize such Intellectual Properties (including the

Licensed Intellectual Property) which Seller has rights to use as of the Closing Date, after obtaining any and all consents necessary therefor for Purchaser to be able to operate the Business substantially in the manner as such Business was operated by Seller. For this purpose, Purchaser shall enter into one or more assignment and licensing agreements (the "IP Assignment and

Licensing Agreements") with the holders of relevant Intellectual Properties, including Seller itself, prior to the Closing. All costs, if any, shall be payable by Seller to any third parties in connection with the transfer, licenses or sub-licenses for the benefit of Purchaser pursuant to this Agreement."

1.3. Amendment of Section 1.3. "Purchase Price" of the Original Agreement  
2. Amendment of Section 1.3. "Purchase Price" of the Original Agreement.

(a) Section 1.3(a) of the Original Agreement (on page 11 of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

"The total aggregate purchase price for the Purchased Assets exclusive of VAT shall be US\$575,000,000 (the "Purchase Price") plus the Assumed Liabilities."

(b) Section 1.3(b) of the Original Agreement (on page 11 of the Original Agreement) is hereby deleted.

(c) Immediately following the first paragraph in Section 1.3(c) of the Original Agreement (on pages 11 of the Original Agreement), the following shall be added:

"In the event that such ruling by the Korean tax authority shall be issued to the effect that the transaction contemplated hereunder and under the Original Agreement shall be VAT-payable, Purchaser shall pay the amount equal to the Purchase Price to Seller at Closing, out of which Seller shall pay the VAT amount to be payable in accordance with the relevant VAT law of Korea ("Payable VAT") to the relevant Korean tax authority when due, and shall immediately provide a copy of the receipt to Purchaser. When Purchaser actually receives the refund of the VAT in the amount of the Payable VAT from the relevant tax office, Purchaser shall immediately deposit the same amount to an Escrow Account or a bank account designated by Seller's creditor banks for the repayment of debt by Seller to its creditor banks. Deposit by Purchaser of the refunded VAT shall discharge ATK's obligation to pay the Purchase Price irrespective of whether such refunded VAT amount is less than Payable VAT.

In the event that the ruling by the Korean tax authority shall be issued to the effect that the transaction contemplated hereunder and under the Original Agreement shall be VAT-exempt, Purchaser shall not withhold any amount from the Purchase Price in connection with the VAT."

(d) Section 1.3(d) of the Original Agreement (on pages 12 through 13 of the Original Agreement) is hereby deleted in its entirety and the following shall be substituted therefor:

"(d) On or prior to the Closing Date, Seller, Purchaser and an escrow agent to be appointed by mutual consent of Seller and Purchaser ("Escrow Agent") shall enter into one or more escrow agreements ("Escrow Agreements") in such form and substance to be mutually agreed by the Parties. Such portion of the Purchase Price as provided in Section 1.4(b) shall be deposited with one or more escrow accounts ("Escrow Accounts") to assure the repayment of certain liabilities by Seller, and released to its creditors in accordance with the terms of the Escrow Agreements."

1.4. Amendment of Section 1.4. "Payment of Purchase Price" of the Original Agreement2Amendment of Section 1.4. "Payment of Purchase Price" of the Original Agreement.

(a) Section 1.4(a) of the Original Agreement (on page 12 of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

"(a) Purchaser's payment at the Closing of the amount which shall be set forth in Schedule 1.4(a), by wire transfer or delivery of a certified bank check immediately available and in accordance with the instructions of Seller;"

(b) Section 1.4(b) of the Original Agreement (on page 12 of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

"(b) Purchaser's deposit at the Closing into an Escrow Account of the amount which shall be set forth in Schedule 1.4(b);"

(c) Section 1.4(c) of the Original Agreement (on page 12 of the Original Agreement) is hereby deleted.

1.6 Amendment of Section 1.6 "Adjustments to Purchase Price" of the Original Agreement.

(b) Section 1.6.(b) of the Original Agreement (on pages 13 through 14) is hereby deleted and the following shall be replaced therefor:

"(b) Adjustment Formula.

If the Net Asset Value at the Closing Date is less than the Net Asset Value as of the Balance Sheet Date (without considering the depreciation between the Closing Date and the Balance Sheet Date), then, the Purchase Price shall be reduced by the amount of such deficiency accordingly. In order to give effect to any such reduction, the Purchaser, at the Purchaser's option, may demand Seller to compensate for such deficiency by requiring payments or delivery of additional assets having values equivalent to such deficiency within 15 days from the date of discovery of such deficiency by the Purchaser, or, alternatively, withholding of such deficient amount from any amount owing to Seller by Purchaser or its Affiliates to the extent permissible under Korean law."

1.8. Amendment of Section 1.8 "Conditions to Each Party's Obligations" of the Original Agreement.

(a) The first sentence of Section 1.8(a) of the Original Agreement (on page 16 of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

"(a) The Escrow Agreement, the IP Assignment and Licensing Agreements (or any equivalent thereof), the Transition Service Agreement, the assignment agreement provided in Section 1.10(b) hereof, and any other agreements, if any, necessary to vest in Purchaser good, valid and marketable title to the Purchased Assets (collectively, the "Ancillary Agreements") have been duly executed and delivered after having been duly authorized by all necessary corporate actions by the relevant parties thereto."

1.10 Amendment of Section 1.10 "Conditions to Purchaser's Obligations" of the Original Agreement.

(h) Section 1.10(h) of the Original Agreement (on page 19 of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

"(h) After (i) Amkor shall have been satisfied with the results of their due diligence, (ii) Amkor shall have entered into an arrangement satisfactory to Amkor in its sole discretion, to finance the Purchase Price in full, (iii) Amkor shall have received a fairness opinion with respect to the terms of the transactions contemplated by this Agreement, (iv) Amkor shall have received a tax exemption under the Foreign Capital Promotion Law in regard to its purchase of the Business ("Tax Exemption"), and (v) the Board of Directors of Amkor shall have

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determined that the transactions contemplated herein are in the best interest of Amkor and Purchaser in light of all circumstances associated with Seller and the transactions contemplated hereby."

(i) Section 1.10(i) of the Original Agreement (on page 19 of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

"(i) Purchaser shall have a right of first refusal if Seller intends to sell any of K1, K2, K3 or the wafer fabrication facilities to any third party;"

1.11. Amendment of Section 1.11 "Closing" of the Original Agreement.

Section 1.11 of the Original Agreement (on page 20 of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

"The closing under this Agreement will take place at such other time, date or place as the Parties shall mutually agree (the "Closing"). The date on which Closing occurs is sometimes referred to herein as the "Closing Date."

1.12. Amendment of Section 1.12 "Deliveries and Proceedings at 2

1.12. Amendment of Section 1.12 "Deliveries and Proceedings at Closing" of the Original Agreement.

(b) Section 1.12(b)(i) and (ii) of the Original Agreement (on page 21 of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

"(i) payment of the amount stated in Schedule 1.4(a);

(ii) a certificate evidencing the deposit of the amount stated in Schedules 1.4(b) with the Escrow Account;"

2.6. Amendment of Section 2.6. "No Changes" of the Original Agreement.

The second sentence of Section 2.6 of the Original Agreement (on page 27

of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

"Without limiting the generality of the foregoing sentence, there has not been:"

2.13. Amendment of Section 2.13. "Consent" of the Original

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Agreement.

The reference of "Schedule 2.10" in Section 2.13 of the Original Agreement (on page 36 of the Original Agreement) is hereby deleted and "Schedule 2.13" shall be substituted therefor.

2.22. Amendment of Section 2.22. "Insurance" of the Original Agreement.

The entire paragraph under Section 2.22 of the Original Agreement (on pages 42 through 43 of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

"Attached hereto as Schedule 2.22 is a complete and correct list of all policies of insurance relating to the Business or the Purchased Assets of which Seller is the owner, insured or beneficiary, or covering any of the property of the Business, true, correct and complete copies of which have been delivered to Purchaser, indicating for each policy the carrier, the insured, type of coverage, the amounts of coverage, deductible, premium rate, cash value if any, expiration date and any pending claims thereunder. All such policies are in full force and effect. The coverage provided by such policies are reasonable, in both scope and amount, in light of the risks attendant to the Business and the Purchased Assets. Seller has paid-in-full all premiums due on such policies as of the Closing Date. There is no default with respect to any provision contained in any such policy, nor has there been any failure to give any notice or present any claim under any such policy in a timely fashion or in the manner or detail required by the policy. Except as set forth on Schedule 2.22, there are no outstanding unpaid premiums or claims under such policies. No notice of cancellation or non-renewal with respect to, or disallowance of any claim under, any such policy has been received by Seller. Except as set forth on Schedule 2.22, Seller has not been refused any insurance, nor has its coverage been limited by any insurance carrier to which it has applied for insurance or with which it has carried insurance during the last five years."

4.2 Amendment of Section 4.2 "Employees of the Business" of the Original Agreement.2

4.2 Amendment of Section 4.2 "Employees of the Business" of the Original Agreement.

The first sentence under Section 4.2(b) of the Original Agreement (on page 46 of the Original Agreement) is hereby deleted and the following shall be substituted

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therefor:

"With respect to the Transferred Employees who elect to terminate their

employment with Seller and commence new employment relation with Purchaser, Seller shall pay, in a timely manner in accordance with the requirements of the Labor Standards Act and current company practices, all salary, bonuses, allowances, severance, unused leave (including the pro rata portion of accrued but unused leave attributable to the portion of the 1999 calendar year prior to closing) and any other monetary obligations or claims relating to the Transferred Employees' employment with Seller or its Affiliates that may have accrued to those personnel prior to their separation."

4.7 Amendment of Section 4.7 "Transition Services" of the Original Agreement.

The entire paragraph under Section 4.7(a) of the Original Agreement (on page 53 of the Original Agreement) is hereby deleted and the following shall be substituted therefor:

"(a) During a certain period from the Closing Date (the "Transition Period") to be separately agreed by the Parties, Seller shall ensure that the Business is continued to be provided with all of the services and parts and components currently provided to the Business by Seller or any Person affiliated with Seller including, among other things, the research and development, accounting, data processing, materials procurement, electronic data processing, administrative services and all other such support services as are reasonably required in connection with the operation of the Business, on the terms and conditions not less favorable than the terms and conditions pursuant to which such services and parts and components are now being provided to the Business. Purchaser shall pay a reasonable fee for the services to be provided by Seller during the Transition Period, as mutually agreed by the Parties. Prior to the Closing, Seller and Purchaser shall enter into a service agreement ("Transition Service Agreement") to ensure such continued services during the Transition Period, in such form and substance as attached hereto as Schedule 4.7."

5.11 Amendment of Section 5.11 "Arbitration" of the Original Agreement.

Section 5.11 (a) of the Original Agreement (on page 59 of the Original Agreement) is hereby deleted in its entirety and the following shall be substituted therefor.

"(a) Any dispute arising under this Agreement which is not settled after good faith attempts by the Parties to amicably resolve such dispute shall be resolved by final and binding arbitration. The arbitration shall be held in Seoul, Korea if the arbitration is brought by Purchaser and in [San Francisco, C.A.], United States of America if the arbitration is brought by Seller in accordance with the Rules of Conciliation and Arbitration of the International Chamber of Commerce ("ICC Rules") as then existing and shall be heard and determined by an arbitral tribunal composed of three (3) arbitrators. Each of the Parties shall appoint one arbitrator each, and both of such arbitrators shall appoint a third arbitrator who shall serve as the Chairman of such arbitral tribunal, provided that such third arbitrator is not a citizen of the U.S.A. or Korea. If either Party fails or decides against appointing an arbitrator within a period of thirty (30) days of the appointment of the first arbitrator, or if the arbitrators designated by the Parties fail or otherwise are unable to appoint the third arbitrator within (30) days of the appointment of the second arbitrator, then the remaining arbitrator(s) shall be selected by the President of the International Chamber of Commerce, U.S.A., which shall act as the appointing authority."



IN WITNESS WHEREOF, the Parties have caused this AMENDMENT to be signed in their respective names by an officer thereof duly authorized as of the date first above written.

Amkor Technology, Inc.

By: \_\_\_\_\_  
Name:  
Title:

Anam Semiconductor, Inc.

By: \_\_\_\_\_  
Name:  
Title:

## INTELLECTUAL PROPERTY TRANSFER AND LICENSE AGREEMENT

THIS INTELLECTUAL PROPERTY TRANSFER AND LICENSE AGREEMENT (the "Agreement") is entered into effective as of May 6, 1999 (the "Effective Date"), by and between Amkor Technology Korea, Inc. ("Amkor"), a corporation organized under the laws of the Republic of Korea, and Anam Semiconductor, Inc. ("Anam"), a corporation organized under the laws of the Republic of Korea and having offices in Seoul, Korea (each of Amkor and Anam, a "Party"; together, the "Parties").

## W I T N E S S E T H:

WHEREAS, the Parties have entered into that certain "Asset Purchase Agreement" dated as of December 30, 1998, pursuant to which Amkor shall acquire from Anam certain assets related to Anam's K4 packaging facility;

WHEREAS, In connection with such acquisition, Amkor will acquire certain intellectual property rights and license certain other intellectual property rights from Anam;

WHEREAS, Anam will license from Amkor certain intellectual property rights.

NOW, THEREFORE, in consideration of the mutual covenants and promises contained herein, the Parties hereby agree as follows:

ARTICLE 1.  
CONSTRUCTION AND DEFINITIONS

## SECTION 1.1. Construction.

(a) All references in this Agreement to "Articles," "Sections" and "Exhibits" refer to the articles, sections and exhibits of this Agreement.

(b) As used in this Agreement, neutral pronouns and any variations thereof shall be deemed to include the feminine and masculine and all terms used in the singular shall be deemed to include the plural, and vice versa, as the context may require.

(c) The words "hereof," "herein" and "hereunder" and other words of similar import refer to this Agreement as a whole, as the same may from time to time be amended or supplemented, and not to any subdivision contained in this Agreement.

(d) The word "including" when used herein is not intended to be exclusive and means "including, without limitation."

## SECTION 1.2. Definitions. As used herein:

(a) "Anam Facilities" means Anam's "K1," "K2" and "K3" semiconductor packaging facilities located in and around Seoul, Korea.

(b) "Bankruptcy Event" means any of the following events or circumstances with respect to a Party: such Party (i) ceases conducting its business; (ii) makes a general assignment for the benefit of its creditors; (iii) petitions, applies for, or suffers or permits with or without its consent

the appointment of a custodian, receiver, trustee in bankruptcy or similar officer for all or any substantial part of its business or assets; or (iv) avails itself or becomes subject to any proceeding under the U.S. Bankruptcy Code or any similar state, federal or foreign statute relating to bankruptcy, insolvency, reorganization, receivership, arrangement, adjustment of debts, dissolution or liquidation, which proceeding is not dismissed within sixty (60) days of commencement thereof.

(c) "Change of Control" means, with respect to a Party: (A) the direct or indirect acquisition of either (i) the majority of the voting stock of such Party or (ii) all or substantially all of the assets of such Party, by another entity in a single transaction or series of related transactions; or (B) such Party is merged with, or into, another entity.

(d) "Confidential Information" means (i) any information disclosed by one Party (the "Disclosing Party") to the other (the "Receiving Party"), which, if in written, graphic, machine-readable or other tangible form is marked as "Confidential" or "Proprietary", or which, if disclosed orally or by demonstration, is identified at the time of initial disclosure as confidential and reduced to a writing marked "Confidential" and delivered to the Receiving Party within thirty (30) days of such disclosure; and (ii) the terms of this Agreement as set forth in Section 8.3.

(e) "Intellectual Property Rights" means all rights of a Person in, to, or arising out of: (i) any U.S., international or foreign patent, utility model or registered design or any application therefor and any and all reissues, divisions, continuations, renewals, extensions and continuations-in-part thereof; (ii) inventions (whether patentable or not in any country), invention disclosures, improvements, trade secrets, proprietary information, know-how, technology and technical data; (iii) copyrights, copyright registrations, mask works, mask work registrations, and applications therefor in the U.S. or any foreign country, and all other rights corresponding thereto throughout the world; (iv) moral rights; and (v) any other proprietary rights anywhere in the world similar to those described in this definition, including, without limitation, rights in registered computer programs.

(f) "License Term" means the time period commencing on the Effective Date and ending on the earlier of the expiration or termination of that certain "Packaging & Test Services Agreement" by and among Amkor Technology, Inc., Amkor Electronics, Inc., C.I.L. Limited, Anam USA, Inc. and Anam Industrial Co., Ltd.

(g) "Person" means any legal person or entity, including any individual, corporation, partnership, joint venture, association, joint stock company, trust, unincorporated association, limited liability corporation, governmental entity, or other person or entity of similar nature.

(h) "Subsidiary" of a first entity means any corporation or other entity that is directly or indirectly controlling, controlled by or under common control with such first entity.

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For the purpose of this definition, "control" shall mean the direct or indirect ownership of fifty percent (50%) or more of the shares of the subject entity entitle to vote in the election of directors (or, in the case of an entity that is not a corporation, for the election of managing authority).

(i) "Term" means the term of this Agreement as set forth in Section 11.1.

(j) "Type A Materials" means those documents and other materials listed on Exhibit B attached hereto and all derivative works and compilations thereof.

(k) "Type A Patents" means the patents listed on Exhibit A attached hereto, the patent applications listed on Exhibit D attached hereto, all patents issuing therefrom and all reissues, renewals, extensions, continuations, continuations-in-part, divisions and reexaminations thereof and foreign and domestic counterparts of all of the foregoing.

(l) "Type B Materials" means all materials, documents, information and data of Anam ("Materials") relating to the K4 packaging facility and all other Materials provided to or learned by Amkor.

(m) "Type B Patents" means all patents and patent applications owned or controlled by Anam, and all reissues, renewals, extensions, continuations, continuations-in-part, divisions and reexaminations thereof and foreign and domestic counterparts of all of the foregoing, other than Type A Patents, including the patents and patent applications listed on Exhibit E attached hereto.

## ARTICLE 2. TYPE A PATENTS

SECTION 2.1. Assignment to Amkor. Anam hereby irrevocably transfers, conveys and assigns to Amkor in perpetuity all worldwide right, title and interest in and to the Type A Patents. In furtherance of the foregoing, upon Amkor's request, Anam shall execute and deliver to Amkor a patent assignment substantially in the form attached hereto as Exhibit C.

SECTION 2.2. License to Anam. Amkor hereby grants to Anam a royalty-free, nonexclusive, worldwide, transferable, sublicensable, royalty-free license under the Type A Patents during the License Term to make in the Anam Facilities, use, sell and import any product and practice any process in the Anam Facilities.

## ARTICLE 3. TYPE B PATENTS

SECTION 3.1. License to Amkor. Anam hereby grants to Amkor and its Subsidiaries a royalty-free, perpetual, irrevocable, nonterminable, nonexclusive, worldwide, transferable, sublicensable, royalty-free license under the Type B Patents to make, have made, use, sell, offer for sale and import any product and practice any process.

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## ARTICLE 4. TYPE A MATERIALS

SECTION 4.1. Assignment to Amkor. Anam hereby irrevocably transfers, conveys and assigns to Amkor in perpetuity all worldwide right, title and interest in and to the Type A Materials, including without limitation (i) Anam's trade secret rights in the information contained in the Type A Materials, (ii) Anam's copyrights and maskwork rights in the Type A Materials, (iii) the right to file in Amkor's name patents on inventions disclosed in the Type A Materials and any other application for or registration of any Intellectual Property Right in or to any of the Type A Materials in Amkor's sole discretion, and (iv) all other Intellectual Property Rights in and to any of the Type A Materials (collectively, the "Type A IP").

SECTION 4.2. Confidential Information. The information contained in the Type A Materials is and shall become Amkor's Confidential Information.

SECTION 4.3. License to Anam. Amkor hereby grants to Anam a nonexclusive, worldwide, transferable, sublicensable, royalty-free license under

the Type A IP during the License Term to make in the Anam Facilities, use, sell and import any product and practice in the Anam Facilities any process.

ARTICLE 5.  
TYPE B MATERIALS

SECTION 5.1. License to Amkor. Anam hereby grants to Amkor and its Subsidiaries a royalty-free, perpetual, irrevocable, nonterminable, nonexclusive, worldwide, transferable, sublicensable license under Anam's existing and future Intellectual Property Rights in and to the Type B Materials to make, have made, use, sell, offer for sale and import any product and practice any process.

ARTICLE 6.  
DELIVERY OF MATERIALS

SECTION 6.1. Delivery. Within five (5) days of the Closing (as such term is defined in the Asset Purchase Agreement), Anam shall, in connection with the transfer of the assets of Anam's K4 semiconductor packaging facility to Amkor, deliver to Amkor copies of the Type A Materials and the Type B Materials (the date of such delivery, the "Transfer Date").

ARTICLE 7.  
NEW TECHNOLOGY SHARING

SECTION 7.1. Meeting; Delivery.

(a) The Parties shall hold regular meetings of an engineering council substantially similar to the meetings held by representatives of the K1, K2, K3 and K4 packaging facilities prior to the Effective Date. Anam shall ensure that representatives of Amkor are invited to, and

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given reasonable opportunity to attend, all such meetings and any similar technology sharing meetings.

(b) No less frequently than once per calendar quarter, the Parties shall meet to discuss inventions and know-how ("New Technology") created or acquired by each of the Parties since the last such meeting or, in the case of the first such meeting, since the Transfer Date. With respect to each item of New Technology, upon mutual agreement of the Parties, the Party owning or controlling, as the case may be, such item of New Technology shall (i) disclose such item of New Technology to the other Party and grant such other Party a license under the disclosing Party's intellectual property rights to make, have made, use, sell, offer for sale and import any products and practice any processes. The foregoing obligation shall not apply to any item of New Technology or any Intellectual Property Right owned or controlled by a purchaser of or successor to Amkor, which item or right was not acquired from Amkor.

SECTION 7.2. Jointly Developed Technology. The Parties shall own jointly developed works of authorship and jointly developed inventions, including all Intellectual Property Rights associated therewith, jointly, without a duty to account.

ARTICLE 8.  
CONFIDENTIAL INFORMATION

SECTION 8.1. Confidential Information and Exclusions. Notwithstanding Section 1.2(d), Confidential Information shall exclude information that the Receiving Party can demonstrate:

(a) was independently developed by the Receiving Party without any use of the Disclosing Party's Confidential Information or by the Receiving

Party's employees or other agents (or independent contractors hired by the Receiving Party) who have not been exposed to the Disclosing Party's Confidential Information;

(b) becomes known to the Receiving Party, without restriction, from a source other than the Disclosing Party, which source has no duty of confidentiality with respect thereto;

(c) was in the public domain at the time it was disclosed or becomes in the public domain through no act or omission of the Receiving Party; or

(d) was rightfully known to the Receiving Party, without restriction, at the time of disclosure;

except that neither Section 8.1(a) nor Section 8.1(d) shall be considered in determining whether the Type A Materials is Amkor's Confidential Information.

SECTION 8.2. Confidentiality Obligation. The Receiving Party shall treat as confidential all of the Disclosing Party's Confidential Information. Without limiting the foregoing, the Receiving Party shall use at least the same degree of care which it uses to prevent the disclosure of its own confidential information of like importance, but in no event with less than reasonable care, to prevent the disclosure of the Disclosing Party's Confidential Information.

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Notwithstanding the foregoing, Amkor shall have the right to disclose Anam's Confidential Information to Amkor's Subsidiaries pursuant to an agreement containing provisions at least as protective of such Confidential Information as this Article 8.

SECTION 8.3. Confidentiality of Agreement. Each Party agrees that the terms and conditions, but not the existence, of this Agreement shall be treated as the other's Confidential Information and that no reference to the terms and conditions of this Agreement or to activities pertaining thereto can be made in any form of public or commercial advertising without the prior written consent of the other Party; provided, however, that each Party may disclose the terms and conditions of this Agreement: (i) as required by any court or other governmental body; (ii) as otherwise required by law; (iii) to legal counsel of the Parties; (iv) in connection with the requirements of an initial public offering or securities filing or offering; (v) in confidence, to accountants, banks, and financing sources and their advisors; (vi) in confidence, in connection with the enforcement of this Agreement or rights under this Agreement; or (vii) in confidence, in connection with a merger or acquisition or proposed merger or acquisition, or the like.

SECTION 8.4. Compelled Disclosure. If a Receiving Party believes that it will be compelled by a court or other authority to disclose Confidential Information of the Disclosing Party, it shall give the Disclosing Party prompt written notice so that the Disclosing Party may take steps to oppose such disclosure.

SECTION 8.5. Remedies. Unauthorized use by a Party of the other Party's Confidential Information will diminish the value of such information. Therefore, if a Party breaches any of its obligations with respect to confidentiality or use of Confidential Information hereunder, the other Party shall be entitled to seek equitable relief to protect its interest therein, including injunctive relief, as well as money damages.

SECTION 8.6. Residuals. Each Party shall be free, and each Party hereby grants to the other Party the right, to use for any purpose the Residuals resulting from access to or work with the Confidential Information. "Residuals" means information retained in the unaided memory of an individual who has had

access to Confidential Information without conscious attempt by such individual to memorize such information. Neither Party shall have any obligation to limit or restrict the assignment of any individual who has had access to the other Party's Confidential Information or to pay royalties for any work resulting from the use of Residuals. However, the foregoing shall not be deemed to grant to either Party a license under the other Party's copyrights or patents.

ARTICLE 9.  
WARRANTIES, DISCLAIMERS AND INDEMNITIES

SECTION 9.1. General Warranty. Each Party hereby represents and warrants to the other that: (i) all corporate action on the part of such Party, its officers, directors and shareholders necessary for the authorization of this Agreement and the performance of all obligations of such Party hereunder has been taken; and (ii) this Agreement, when executed and delivered, will be a valid and binding obligation of such Party enforceable in accordance with its terms.

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SECTION 9.2. No Conflict. Each Party hereby represents and warrants to the other that such Party's making of this Agreement and performance hereunder does not and will not violate any agreement existing between such Party and any third party.

SECTION 9.3. Intellectual Property. Anam hereby represents and warrants to Amkor that, to the best of Anam's knowledge: (i) the Type A Materials, the Type B Materials and Amkor's use thereof as authorized herein will not infringe any Intellectual Property Right of any third party; (ii) neither the Type A Materials nor the Type A Patents are subject to any third-party lien or encumbrance; (iii) no third party is infringing or misappropriating or has infringed or misappropriated: (A) any claim of any of the Type A Patents or the Type B Patents or (B) any other Intellectual Property Right in or to the Type A Materials or the Type B Materials; and (iv) all Intellectual Property Rights transferred or licensed to Amkor hereunder are valid and subsisting, and no grounds exist to invalidate or render unenforceable any such Intellectual Property Right.

SECTION 9.4. Disclaimer. EXCEPT AS EXPRESSLY SET FORTH HEREIN, NEITHER PARTY MAKES ANY WARRANTIES OR CONDITIONS, EXPRESS, STATUTORY, IMPLIED, OR OTHERWISE, WITH RESPECT TO ANY PRODUCT OR SERVICE PROVIDED HEREUNDER, AND EACH PARTY HEREBY DISCLAIMS THE IMPLIED WARRANTIES AND CONDITIONS OF NONINFRINGEMENT OF THIRD PARTY RIGHTS, SATISFACTORY QUALITY, MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE WITH RESPECT THERETO.

SECTION 9.5. Indemnity. Anam shall indemnify and hold Amkor, its affiliates and customers harmless from and against all loss, cost, liability, damage and expense suffered or incurred by any of them in connection with any breach by Anam of any warranty set forth herein.

ARTICLE 10.  
LIABILITY LIMITATIONS

SECTION 10.1. Exclusion of Damages. EXCEPT IN CONNECTION WITH A BREACH OF A PROVISION OF ARTICLE 8, IN NO EVENT SHALL EITHER PARTY BE LIABLE TO THE OTHER FOR ANY INDIRECT, SPECIAL, INCIDENTAL OR CONSEQUENTIAL DAMAGES, WHETHER BASED ON BREACH OF CONTRACT, TORT (INCLUDING NEGLIGENCE), PRODUCT LIABILITY, OR OTHERWISE, AND WHETHER OR NOT THE PARTY AGAINST WHOM LIABILITY IS SOUGHT HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGE.

SECTION 10.2. Failure of Essential Purpose. The limitations specified in this ARTICLE 10 shall survive and apply even if any limited remedy specified in this Agreement is found to have failed of its essential purpose.

ARTICLE 11.  
TERM AND TERMINATION

SECTION 11.1. Term. Unless earlier terminated in accordance with Section 11.2, the term ("Term") of this Agreement shall commence on the Effective Date and continue in full force and effect until the Parties agree to mutually terminate this Agreement.

SECTION 11.2. Default. If either Party defaults in the performance of any of its material obligations hereunder, such Party shall use its best efforts to correct such default within thirty (30) days (or such additional time as the Parties may agree) after written notice thereof from the other Party. If any such default cannot be, or is not, corrected within such thirty (30)-day period, then the non-defaulting Party shall have the right, in addition to any other remedies it may have, to terminate this Agreement by giving written notice to the Party in default.

SECTION 11.3. Survival. The following provisions of this Agreement shall survive any expiration or termination hereof: Articles 1, 3, 5, 8, 9, 10, 11, 12 and 13 and Sections 2.1, 4.1 and 4.2.

ARTICLE 12.  
ARBITRATION

SECTION 12.1. Arbitration of Disputes.

(a) Any dispute arising out of, in connection with, or in relation to the interpretation, performance or breach of this Agreement, including any claim based on contract, tort or statute, which is not settled after good faith attempts by the Parties to amicably resolve such dispute shall be resolved by final and binding arbitration. The arbitration shall be held in Seoul, Korea if the arbitration is brought by Amkor and in San Francisco, California, United States of America if the arbitration is brought by Seller in accordance the Rules of Conciliation and Arbitration of the International Chamber of Commerce ("ICC Rules") as then existing and shall be heard and determined by an arbitration tribunal composed of three (3) arbitrators. Each of the Parties shall appoint one arbitrator each, and both of such arbitrators shall appoint a third arbitrator who shall serve as the Chairman of such arbitration tribunal, provided that such third arbitrator is not a citizen of the United States of America or Korea. If either party fails or decides against appointing an arbitrator within a period of thirty (30) days of the appointment of the first arbitrator, or if the arbitrators designated by the Parties fail or otherwise are unable to appoint the third arbitrator within (30) days of the appointment of the second arbitrator, then the remaining arbitrator (s) shall be selected by the President of the International Chamber of Commerce, U.S.A., which shall act as the appointing authority.

(b) All arbitration proceedings shall be conducted in the English language and the arbitration award (the "Award") shall be rendered no later than six (6) months from the commencement of the arbitration or as otherwise provided by the ICC Rules, unless otherwise extended by the arbitration tribunal for no more than an additional six (6) months for reasons that are just and equitable.

(c) The Parties expressly understand and agree that the Award shall be the sole, exclusive, final and binding remedy between them regarding any and all disputes presented to the arbitration tribunal. Each Party hereby



expressly waives any and all rights that such Party may have with respect to a judicial review of the Award in the courts having jurisdiction over the Party (or its assets) against whom the Award is rendered for a judicial acceptance of the Award and an order of enforcement.

(d) Notwithstanding any other provision of this Agreement, either Party shall be entitled to seek preliminary injunctive relief from any court of competent jurisdiction pending the final decision or award of the arbitrators. Any arbitration shall be held before a single arbitrator, who shall be selected in accordance

#### ARTICLE 13. MISCELLANEOUS

SECTION 13.1. Further Assurances. At any time, and from time to time, Anam shall forthwith, upon Amkor's (or its successors' or assigns') request, take any and all steps necessary to execute, acknowledge and deliver to Amkor (or its successors or assigns), any and all further instruments and assurances (including, without limitation, assignments of patent and copyright rights and patent applications) necessary or expedient in order to invest all right, title and interest in the Type A Patents and Type A Materials in Amkor (or its successors or assigns) and to facilitate Amkor's (or its successors' and assigns') enjoyment, enforcement and recordation of such rights. Anam hereby constitutes and appoints Amkor as Anam's true and lawful attorney-in-fact with full power of substitution, in Anam's name, place and stead to take any and all steps, including proceedings at law, in equity or otherwise, to execute, acknowledge and deliver any and all documents, instruments and assurances necessary or expedient in order to vest, record or perfect all Amkor's (or its successors' or assigns') rights in the Type A Patents and Type A Materials, to protect the same, or to enforce any claim or any right of any kind with respect thereto. This includes, but is not limited to, any rights with respect to the Type A Patents and Type A Materials that may have accrued in Anam's favor at any time prior to the date of this Agreement. Anam hereby declares that the foregoing power is coupled with an interest and, as such, is irrevocable. Without limiting the foregoing, Anam shall, upon Amkor's request, provide to Amkor all reasonable cooperation in connection with the application for or registration of Intellectual Property Rights in or to the Type A Patents and/or the Type A Materials, including without limitation cooperation in connection with the prosecution of the patent applications included in the Type A Patents.

SECTION 13.2. Licensors Bankruptcy. All rights and licenses granted to Amkor pursuant to this Agreement are, and shall otherwise be deemed to be, for purposes of Section 365(n) of Title 11 of the United States Code (the "Bankruptcy Code"), licenses to rights of "intellectual property" as defined thereunder. Notwithstanding any provision contained herein to the contrary, if Anam is under any proceeding under the Bankruptcy Code and the trustee in bankruptcy of Anam, or Anam as a debtor in possession, rightfully elects to reject this Agreement, Amkor may, pursuant to Sections 365(n)(1) and (2) of the Bankruptcy Code, retain any and all of Amkor's rights hereunder, to the maximum extent permitted by law, subject to Amkor's making the payments specified herein.

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SECTION 13.3. Governing Law. THIS AGREEMENT SHALL BE GOVERNED BY AND INTERPRETED IN ACCORDANCE WITH THE LAWS OF THE REPUBLIC OF KOREA, WITHOUT REFERENCE TO CONFLICT OF LAWS PRINCIPLES.

SECTION 13.4. Independent Contractors. The Parties are independent contractors. Nothing contained herein or done pursuant to this Agreement shall constitute either Party the agent of the other Party for any purpose or in any sense whatsoever, or constitute the Parties as partners or joint venturers.

SECTION 13.5. Assignment. Anam shall not assign or delegate this

Agreement, or any of its rights or duties hereunder, directly, indirectly, by operation of law, in connection with a Change of Control or otherwise, and any such purported assignment or delegation shall be void, except with the express written permission of Amkor in its sole discretion. Amkor may assign or delegate this Agreement and any of Amkor's rights or duties hereunder in Amkor's sole discretion.

SECTION 13.6. Amendment. No alteration, amendment, waiver, cancellation or any other change in any term or condition of this Agreement shall be valid or binding on either Party unless mutually assented to in writing by both Parties.

SECTION 13.7. No Waiver. The failure of either Party to enforce at any time any of the provisions of this Agreement, or the failure to require at any time performance by the other Party of any of the provisions of this Agreement, shall in no way be construed to be a present or future waiver of such provisions, nor in any way affect the validity of either Party to enforce each and every such provision thereafter. The express waiver by either Party of any provision, condition or requirement of this Agreement shall not constitute a waiver of any future obligation to comply with such provision, condition or requirement.

SECTION 13.8. Severability. If, for any reason, a court of competent jurisdiction finds any provision of this Agreement, or portion thereof, to be invalid or unenforceable, such provision of the Agreement will be enforced to the maximum extent permissible so as to effect the intent of the Parties, and the remainder of this Agreement will continue in full force and effect. The Parties agree to negotiate in good faith an enforceable substitute provision for any invalid or unenforceable provision that most nearly achieves the intent and economic effect of such provision.

SECTION 13.9. Notices. All notices, requests, demands, waivers, and other communications required or permitted hereunder shall be in writing and shall be deemed to have been duly given: (i) when delivered by hand or confirmed facsimile transmission; (ii) one day after delivery by receipted overnight delivery; or (iii) four days after being mailed by certified or registered mail, return receipt requested, with postage prepaid to the following, or to such other person or address as either Party shall furnish to the other Party in writing pursuant to the above:

(a) in the case of notices to Amkor, to the attention of the General Counsel at the relevant address set forth on the first page hereof, with a copy to Selwyn B. Goldberg, Esq., Wilson Sonsini Goodrich & Rosati, 650 Page Mill Road, Palo Alto, CA 94304.

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(b) in the case of notices to Anam, to [ ].

SECTION 13.10. Titles and Subtitles. The titles and subtitles used in this Agreement are used for convenience only and are not to be considered in construing or interpreting this Agreement.

SECTION 13.11. Entire Agreement. The terms and conditions herein contained and the referenced Exhibits which are hereby incorporated herein by reference constitute the entire agreement between the Parties with respect to the subject matter hereof and supersede all previous and contemporaneous agreements and understandings, whether oral or written, between the Parties with respect to the subject matter hereof.

SECTION 13.12. Counterparts. This Agreement may be executed in counterparts or duplicate originals, both of which shall be regarded as one and the same instrument, and which shall be the official and governing version in the interpretation of this Agreement.

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IN WITNESS WHEREOF, the Parties have caused this Agreement to be executed by duly authorized officers or representatives to be effective as of the date first above written.

Amkor Technology, Inc.

Anam Semiconductor, Inc.

By: /s/

By: /s/

Name:

Name:

Title:

Title:

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Exhibit A

HEAT SINK PATENTS

No.	Title	Inventor	Appl No.	Filing Date	Reg. Date	Patent	Assignee	Remark
AP-094	Semiconductor package having heatsink and method of manufacturing it (Heatsink structure)	D.H. Moon	94-22437	Sep 7, '94	Dec 26, '97	P137066	Anam	
AP-108	Semiconductor package (Making heatsink when it's easy to eject in molding process)	W.S. Shin	94-25862	Oct 10, '94	Dec 26, '97	P134933	Anam	
AP-109	A method of manufacturing for semiconductor package (Attaching heatsink at last time)	J.Y. Jung	94-25863	Oct 10, '94	Jan 23, '98	P137325	Anam	
AP-111	Apparatus of attaching tape for preventing heatsink plating	L.H. Kim	94-27136	Oct 24, '94	Mar 31, '98	P144313	Anam	
AP-114	Method of attaching between heatsink and leadframe of semiconductor package	B.T. Dho	94-28904	Nov 4, '94	May 22, '98	P159965	Anam	
AU-128	Structure of heatspreader for semiconductor package	K.J. Kim	94-33576	Dec 10, '94	Jan 23, '98	U117453	Anam	

AP-181	Method of eliminating tape attached in heatsink	L.H. Kim	94-39353	Dec 30, '94	Feb 26, '98	P142135	Anam	
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#### BGA PATENTS

No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent	Assignee	Remark
AP-027	Semiconductor package (BGA + PQ)	N.H. Kwak	93-27078	Dec 9, '93	Sep 25, '97	P127737	Anam	
AP-091	Cap type BGA package and method of manufacturing it	Y.W. Heo	94-21781	Aug 31, '94	Mar 31, '98	P144311	Anam	

#### LEADFRAME PATENTS

No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent	Assignee	Remark
AP-035	Surface mounting integrated circuit package (BLP)	G. Lee	94-01773	Jan 31, '94	Sep 12, '97	P124790	Anam	
45	Plastic mold package with heatsink	Rorert	94-05545	Mar 19, '94	Jun 30, '97	P126052		

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No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent	Assignee	Remark
46	Forming method of plastic mold package with heatsink	Rorert	94-05546	Mar 19, '94	Jun 30, '97	P126053		

#### PKG PATENTS

No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent	Assignee	Remark
1	Safe setting method for solder ball for integrated circuit package (BGA)		93-15983			P105750		
2	Method of decreasing bending for integrated circuit package (BGA)		93-15984			P122789		
3	Mold runner removal from a substrate-based packaged electronic device (BGA, Gold gate)		93-15985			P128174		
4	Semiconductor package (BGA+PQ)		93-27078			P127737		
5	Method of mounting chip for BGA semiconductor package and structure using the same (Double Adhesive)		94-02982			P131392		
6	Cap type BGA package and method of manufacturing it		94-21781			P144311		
7	Method for checking wire bonding in result of BGA package		94-24280			P131389		
8	Semiconductor package (Consists of metal cap and advanced adhesive)		94-39354			P167141		
9	Method for leveling solder ball array in BGA semiconductor package		95-10418			P179473		
11	BGA semiconductor package with improved heat dissipation and dehumidification		95-19582			P159987		
19	Printed circuit board having epoxy barrier around its throughout slot and ball grid array semiconductor package using such a printed circuit board, thereby exhibiting a high moisture discharge characteristic		95-37513			P170024		
119	Method of decreasing bending for integrated circuit package (BGA)		97-10103			P122847		

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## Exhibit B

## Type A Materials

I. All documents, databases and other materials in Anam's possession or control, whether in printed, electronic or other form, describing, addressing, related to or useful in connection with any of the following topics:

A. With respect to TSOP/TSSOP/SSOP:

1. General leadframe design rules including strip configurations and die design guidelines.
2. Wafer Backgrinding process recipe for optimized surface finish and residual stress.
3. Leadframe design criteria specific to ePad TSSOP delamination control.
4. Low loop and second stitch on ball wire bonding process recipes.
5. Dispense tool design criteria for thermally enhanced epoxy processing.
6. ePad TSSOP deflashing process and recipe.
7. ePad process flow for delamination enhancement.

B. Generally:

1. Tape design rules, including with respect to lead length/notch width, reliability, yield and quality.
2. Tape to frame lamination material and process.
3. Elastomer material, including with respect to thickness, supplier, type, reliability and manufacturability.
4. Frame design, including with respect to cost reduction.
5. Elastomer to tape to die size design rules, including issues with respect to quality and yield optimization.
6. Multiple unit punching of elastomer onto tape sites, including with respect to cost reduction.
7. D/A process and optimization methodology, including with respect to time/press/temp to meet MRT.

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8. Lead bond parameters (90E and 45E leads) (to allow reliable perf)
9. Coverlay tape material, including with respect to specific adhesion level but with release properties.
10. Coverlay tape attach process (void free).
11. Encap material prep, including with respect to filtering/mixing.

12. Encap dispense/vacuum/cure process (high speed/void free).
13. Solderball attach process, including with respect to small balls and multiple units on strip.
14. Mark (laser mark on Si backside without die damage).
15. Singulation (process parameters to avoid burrs).

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II. The following drawings and all information contained therein:

DRAWING #	TITLE
001 0501 2099	BGA Standard Process Description
001 0307 2025	Saw and Clean Monitor
001 0510 2495	Precure Process (before die attach)
001 0310 2033	Die Mounting Monitor
001 0311 2078	Ball Shear Test
001 0311 2465	Bond Strength Test
001 0311 2455	Wire Bond Monitor
001 0314 2032	Oven Monitor
001 0410 2637	Incoming Inspection for Die Attach Adhesive
001 0411 2694	Incoming Inspection for Bonding Wires
001 0440 2688	Incoming Inspection for PCB
001 0506 2001	Wafer Mounting Process
001 0507 2002	Wafer Sawing Process
001 0510 2042	Die Bonding for Adhesive
001 0510 2052	Adhesive Curving Process

001 0511 2044	Wire Bonding for Gold Wire
001 0511 2497	Precure Process (before wire bond)
001 0517 2496	Precure Process (before mold)
001 0417 2690	Incoming Inspection for Mold Compound
001 0513 2005	Internal Visual Inspection for Commercial Product

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001 0313 2009	Internal Visual Lot Acceptance
001 0419 2671	Incoming Inspection for Marking/Dot Ink
001 0517 2447	Process for Molding
001 0317 2476	Mold Monitor
001 0217 2223	X-Ray Monitor Mold
001 0519 2062	Laser Marking
001 0319 2105	Laser Marking Monitor

DRAWING #	TITLE
001 0519 2062	Marking
001 0319 2105	Marking Monitor
001 0514 2038	Post Mold Cure
001 0314 2032	Oven Monitor
001 0319 2472	Marking Permanency Test
001 0431 2083	Procurement Spec for Shipping Tray
001 0340 2482	Solder Ball Attach Monitor
001 0340 2481	Solder Ball Shear Strength Test
001 0521 2014	DTFS for Plastic Packages
001 0422 2666	Anode & Solder Incoming Inspection
001 0540 2624	Solder Ball Attach Process
001 0321 2259	DTFS Monitor (Deflash/Trim/Form/Singulation)
001 0530 2623	Final Visual Inspection
001 0330 2010	Final V/M Lot Acceptance

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001 0531 2247	Dry Packing
001 0331 2248	Dry Packing Monitor
001 0531 2234	Packing Operation Procedure
001 0331 2158	Packing Monitor
BODY SIZE	STRIP DRAWING #
13 X 13	72132
14 X 22	72076
15 X 15	72371
17 X 17	72176
23 X 23	70821
27 x 27	70795
31 x 31	71218
35 x 35	70796
37.5 x 37.5	75312

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Exhibit C

Patent Assignment

ASSIGNMENT OF PATENT RIGHTS

For good and valuable consideration, the receipt of which is hereby acknowledged, \_\_\_\_\_, a \_\_\_\_\_ corporation, having offices at \_\_\_\_\_ ("Assignor"), does hereby sell, assign, transfer and convey unto \_\_\_\_\_, a



\_\_\_\_\_ corporation, having offices at \_\_\_\_\_ ("Assignee") or its designees, all of Assignor's right, title and interest in and to the patent applications and patents listed below, any patents issuing on any patent applications listed below, the inventions disclosed in any of the foregoing, any and all counterpart United States, international and foreign patents, applications and certificates of invention based upon or covering any portion of the foregoing and all reissues, divisionals, renewals, extensions, provisionals, continuations and continuations-in-part of any of the foregoing (collectively "Patent Rights"):

PATENT OR APPLICATION NUMBER	COUNTRY	ISSUE OR FILING DATE	TITLE AND INVENTOR(S)
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Assignor represents, warrants and covenants that: (i) it is the sole owner, assignee and holder of record title to the Patent Rights identified above, (ii) it has obtained and properly recorded previously executed assignments for all patent applications and patents identified above as necessary to fully perfect its rights and title therein in accordance with governing law and regulations in each respective jurisdiction, and (iii) it has full power and authority to make the present assignment. Assignor shall indemnify and hold harmless Assignee for any breach of the foregoing.

Assignor further agrees to and hereby does sell, assign, transfer and convey unto Assignee all rights: (i) in and to causes of action and enforcement rights for the Patent Rights including all rights to pursue damages, injunctive relief and other remedies for past and future infringement of the Patent Rights, and (ii) to apply in any or all countries of the world for patents, certificates of invention or other governmental grants for the Patent Rights, including without limitation under the Paris Convention for the Protection of Industrial Property, the International Patent Cooperation Treaty, or any other convention, treaty, agreement or understanding. Assignor also hereby authorizes the respective patent office or governmental agency in each jurisdiction to issue any and all patents or certificates of invention which may be granted upon any of the Patent Rights in the name of Assignee, as the assignee to the entire interest therein.

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Assignor will, at the reasonable request of Assignee and without demanding any further consideration therefor, do all things necessary, proper, or advisable, including without limitation the execution, acknowledgment and recordation of specific assignments, oaths, declarations and other documents on a country-by-country basis, to assist Assignee in obtaining, perfecting, sustaining, and/or enforcing the Patent Rights. Such assistance shall include providing, and obtaining from the respective inventors, prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, powers of attorney, specifications, declarations or other papers and other assistance reasonably necessary for filing patent applications, complying with any duty of disclosure, and conducting prosecution, reexamination, reissue, interference or other priority proceedings, opposition proceedings, cancellation proceedings, public use proceedings, infringement or other court actions and the like with respect to the Patent Rights.

The terms and conditions of this Assignment shall inure to the benefit of Assignee, its successors, assigns and other legal representatives, and shall be binding upon Assignor, its successor, assigns and other legal representatives.

IN WITNESS WHEREOF this Assignment of Patent Rights is executed at \_\_\_\_\_,  
on \_\_\_\_\_.

ASSIGNOR

By:

\_\_\_\_\_  
Name:

(Notarization Required)

\_\_\_\_\_  
Title:

\_\_\_\_\_  
Name

State of \_\_\_\_\_ )  
County of \_\_\_\_\_ )

\_\_\_\_\_  
Date

On \_\_\_\_\_, 1997, before me, \_\_\_\_\_,  
personally appeared \_\_\_\_\_,  
[ ] personally known to me or [ ] proved  
to me on the basis of satisfactory  
evidence, to be the person whose name is  
subscribed to the within instrument and  
acknowledged to me that he/she executed  
the same in his/her authorized capacity,  
and that by his/her signature on the  
instrument the person or the entity upon  
behalf of which the person acted,  
executed the instrument.

WITNESS my hand and official seal.

\_\_\_\_\_  
(Notary Public)

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Exhibit D

Patent Applications

HEAT SINK PATENTS

No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent	Assignee	Remark
AU-278	Heatsink structure for semiconductor package (Forming a plural of Ni/Pd layer on heatsink)	W.S. Shin	95-34075	Nov 17, '95	Aug 28, '98		Anam	Notice of Allowance

AP-392	Structure of semiconductor package (Making ground ring at the heatsink)	L.S. Yoon	96-06301	Mar 11, '96	Oct 30, '98		Anam	Notice of Allowance
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BGA PATENTS

No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent	Assignee	Remark
AP-242	BGA semiconductor package circuit board structure of using the solderballs as I/O part	W.Y. Pyo	95-25173	Aug 16, '95	Nov 9, '98		Anam	Notice of Allowance
AP-296	Humidity per coating prevention	Y.W. Heo	95-54766	Dec 22, '95	Sep 11, '98		Anam	Notice of

	structure of BGA semiconductor package						Allowance	
AP-390	Structure of BGA semiconductor package and method of manufacturing the same (CSP BGA)	Y.W. Heo	96-05344	Feb 29, '96	Oct 30, '98		Anam	Notice of Allowance
AP-400	Structure of PCB substrate of BGA semiconductor package	Y.M. Kim	96-09779	Apr 1, '96	Nov 27, '98		Anam	Notice of Allowance
AP-401	BGA semiconductor package	M.E. Lee	96-09780	Apr 1, '96	Nov 27, '98		Anam	Notice of Allowance
AP-545	The Structure of semiconductor package (BGA - Using half-etching & one-side molding)	D.J. Kim	96-62306	Dec 6, '96			Anam	
AP-576	BGA semiconductor package built-in carrier frame	L.K. Shin	96-77898	Dec 30, '96			Anam	

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No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent	Assignee	Remark
AP-577	BGA semiconductor package with carrier frame	L.K. Shin	96-77899	Dec 30, '96			Anam	
AP-610	BGA semiconductor package with heatsink	L.K. Shin	97-02503	Jan 28, '97			Anam	
AP-612	Free-delamination pad for BGA semiconductor package	L.K. Shin	97-02505	Jan 28, '97			Anam	
AP-613	BGA semiconductor package with heatsink	Y.M. Kim	97-02506	Jan 28, '97			Anam	
AP-615	BGA semiconductor package using the flexible circuit board	Y.W. Heo	97-04430	Feb 14, '97			Anam	
AP-616	The method of forming solder-ball land and BGA semiconductor package including the same	L.K. Shin	97-04431	Feb 14, '97			Anam	
AP-916	Molding device of ball grid array semiconductor using a carrier frame	S.G. Lee	98-37203	Sep 9, '98			Anam	
AP-919	Attaching method of flexible circuit board on carrier frame for ball grid array semiconductor package	S.H. Ha	98-37630	Sep 11, '98			Anam	
AP-923	Structure of BGA semiconductor packages with cavity down type	D.H. Park	98-37970	Sep 15, '98			Anam	
AP-926	Structure of ball grid array semiconductor package using flexible circuit board strip	L.G. Ham	98-38259	Sep 16, '98			Anam	

#### LEADFRAME PATENTS

No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent	Assignee	Remark
AP-233	Structure of semiconductor package (Paddleless)	W.S. Shin	95-19587	Jul 5, '95	Nov 9, '98		Anam	Notice of Allowance
AP-397	Semiconductor package and method of manufacturing the same (BLP)	W.S. Shin	96-09776	Apr 1, '96	Nov 30, '96		Anam	Notice of Allowance
AP-649	Area array bumped semiconductor package	W.S. Shin	97-18509	May 13, '97			Anam	
AP-650	The method forming area array burned semiconductor package	W.S. Shin	97-18510	May 13, '97			Anam	

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No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent	Assignee	Remark
AP-660	Grid array leadframe and lead grid array semiconductor package using the same	L.K. Han	97-24409	Jun 12, '97			Anam	
AP-760	Array type semiconductor package using lead frame and its method	S.G. Lee	97-54507	Oct 23, '97			Anam	
AP-762	Array type semiconductor package using lead frame and its method	S.G. Lee	97-54509	Oct 23, '97			Anam	

#### WAFER SCALE PACKAGING

No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent	Assignee	Remark
AP-623	Structure and manufacturing method for flip-ship semiconductor package	S.J. Kim	97-04652	Feb 17, '97			Anam	
AP-763	Semiconductor package for a flip chip and its manufacturing method	S.J. Kim	97-54510	Oct 23, '97			Anam	
AP-959	A flexible film for semiconductor packages	D.S. You	98-47798	Nov 06, '98			Anam	
AP-964	Flexible substrate structure and semiconductor packages and manufacturing method with the structure	S.H. Lee	98-48929	Nov 14, '98			Anam	
AP-761	Ball grid array semiconductor package using a silicon substrate	W.J. Kang	97-54508	Oct 23, '97			Anam	

#### PKG PATENTS

No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent	Assignee	Remark
10	Thin BGA semiconductor package with exposed heatsink		95-25172					
11	BGA semiconductor package circuit board structure of using the solderballs as I/O part		95-25173					
12	Ball grid array semiconductor package with ring-type heatsink		95-41438					
13	Semiconductor chip bonding method and structure for using solder ball		95-41845					
14	Humidity per coating prevention structure of BGA semiconductor package		95-54766					

No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent	Assignee	Remark
15	Semiconductor package for using solderballs and leads as I/O terminal		95-69093					
16	BGA semiconductor package		95-69098					
17	Structure of BGA semiconductor package and method of manufacturing the same (CSP BGA)		96-05344					
18	Method of producing BGA semiconductor package metal carrier frame and BGA package produced by such method		96-05345					
19	Method of manufacturing semiconductor package and structure produced by such method		96-06302					

(CSP: Making solder bump on chip pad)

20	Semiconductor package and method of manufacturing the same (BLP)	96-09776
21	BGA semiconductor package	96-09777
22	Structure of PCB substrate of BGA semiconductor package	96-09779
23	BGA semiconductor package	96-09780
24	Method of molding BGA semiconductor attached heatsink	96-22903
25	Stacking BGA semiconductor package	96-41464
26	BGA semiconductor package	96-43844
27	BGA semiconductor package	96-62300
28	Semiconductor package	96-62301
29	BGA semiconductor package	96-62302

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No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent No.	Assignee	Remark
30	The structure of semiconductor package (BGA: Using half-etching & one-sided molding)		96-62306					
31	Structure and method of BGA semiconductor package with heatsink		96-65236					
32	Structure and manufacturing method of semiconductor package (Attaching internally double chip on leadframe)		96-74115					
33	The structure of PCB for BGA semiconductor package		96-74117					
34	Printed circuit for ball grid array semiconductor package and method for molding ball grid array semiconductor package using the same		96-74120					
35	BGA semiconductor package built-in carrier frame		96-77898					
36	BGA semiconductor package with carrier frame		96-77899					
37	Flexible circuit board of die flag for BGA semiconductor package		96-77900					
38	Flexible circuit board of die flag for BGA semiconductor package		96-77901					
39	Flexible circuit board of die flag for BGA semiconductor package		96-77902					
40	The structure of semiconductor with carrier frame		96-77931					
41	BGA semiconductor package with heatsink		97-02503					
42	The singulation method of BGA semiconductor package		97-02504					
43	Free-delamination pad for BGA semiconductor package		97-02505					
44	BGA semiconductor package with heatsink		97-02506					
45	BGA semiconductor package using		97-0443 0					

flexible circuit board

46 Semiconductor package (PGA) 97-04432

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No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent No.	Assignee	Remark
47	Semiconductor package (Using the pin-type of metal sheet)		97-04433					
48	BGA semiconductor package		97-04653					
49	Structure and manufacturing method of BGA		97-04656					
50	Ball grid array semiconductor package		97-04657					
51	The structure of semiconductor package		97-06062					
52	Semiconductor package (Attaching heatsink on the top of chip)		97-18551					
53	Semiconductor package (Attaching the leadframe of array type at the bottom of package)		97-18507					
54	Area array bumped semiconductor package		97-18509					
55	The method forming area array bumped semiconductor package		97-18510					
56	Semiconductor package (Making test terminals in circuit test)		97-18623					
57	Semiconductor package (BGA)		97-18624					
58	Semiconductor package (Attaching coupling agent for preventing crack & popcorn from PCB)		97-18629					
59	Ball grid array semiconductor package suing a silicon substrate		97-54508					
60	Array type semiconductor package suing lead frame and its method		97-54509					
61	Printed circuit board of wafer taped chip scale package and method of routing it		97-64123					
62	Ball grid array semiconductor package		97-64125					
63	Structure of micro film for micro ball grid array semiconductor package		97-43970					

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No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent No.	Assignee	Remark
64	Structure of fan-in TAB lead for micro-film for a semiconductor package		97-43971					

65	Structure of micro film for micro ball grid array semiconductor package	97-43972
66	Structure of micro film for micro ball grid array semiconductor package	97-43973
67	Structure of micro film for micro ball grid array semiconductor package	97-43974
68	Structure of micro film for micro ball grid array semiconductor package	97-43975
69	Structure of micro film for micro ball grid array semiconductor package	97-43976
70	Structure of chip array ball grid array semiconductor package	97-79222
71	Ball grid array semiconductor package using a flexible circuit board	97-79225
72	Ball grid array semiconductor package using a flexible circuit board	97-79228
73	Singulation method of ball grid array semiconductor package using a flexible circuit board strip	97-79230
74	Ball grid array semiconductor package using a flexible circuit board and its manufacturing method	97-79232
75	Semiconductor package	98-12364
76	Structure of semiconductor package	98-09915
77	Structure of BGA-semiconductor package	98-09916
78	Printed circuit board for semiconductor package for preventing static electricity	98-36897
79	Printed circuit board for semiconductor package for preventing static electricity	98-36898
80	Attaching method of flexible circuit board on carrier frame for ball grid array semiconductor package	98-37630

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No.	Title	Inventor	Appl No.	Filing Date	Req. Date	Patent No.	Assignee	Remark
81	Structure of BGA semiconductor packages with cavity down type		98-37970					
82	Structure of ball grid array semiconductor package using flexible circuit board strip		98-38259					
83	Micro ball grid array semiconductor package		98-40125					
84	Semiconductor package and its manufacturing method		98-48046					
85	Flexible circuit board and semiconductor packages using it		98-25418					

Exhibit E

Type B Patents

## I. Korean Patents and Applications

APPLICATION NO.	TITLE	INVENTOR	APPLICATION DATE	ISSUE NO.
87-15336	Marking apparatus of leadframe for assembling semiconductor	J.H. Choi	87/9/8	U0 49666
91-16361	Pad cleaner of marking machine for semiconductor device	S.M. Choi	91/9/19	P0 70556
91-16589	Method and apparatus of lead bending for surface mounting device	Y.H. Kang	91/9/24	P0 81093
91-22233	Method and apparatus of cam form for IC package	K.C. Park	91/12/5	P0 81833
92-03869	Method and apparatus of Forming for surface mounting device	G. Lee	92/3/9	P0 81834

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92-04715	Structure of package for surface mounting device	Y.W. Heo	92/3/25	U0 89814
92-10285	Method and apparatus of LASER marking for IC package	H.Y. Lee	92/6/13	P1 13208
92-10526	Heatspreader fixture	J.Y. Kil	92/6/13	U0 88640
92-26797	Gate cull of quad type intergrated circuit package and gate tiebar of leadframe (QFP, making the structure of gate tiebar for easily trimming process)	G. Lee	92/12/30	P0 95030
92-26798	Matrix structure of dual in line leadframe (PDIP)	Y.W. Heo	92/12/30	P1 05768
93-03199	Automatic leadframe loader	S.Y. Park	93/3/4	P1 05760
93-13930	Apparatus for inspecting leadframe bonding	C.G. Son	93/7/26	U0 94008
93-13931	Apparatus for inspecting intergrated circuit package	H.M. Aha	93/7/26	U0 94009
93-14164	Feeding system for marking intergrated circuit package	S.S. Han	93/7/26	P1 18553
93-15983	Safe setting method for solder ball for integrated circuit package (BGA)	Y.W. Heo	93/8/18	P1 05750
93-15984	Method of decreasing bending for integrated circuit package (BGA)	Y.W. Heo	93/8/18	P1 22789
93-15986	Apparatus of eliminating gate for intergrated circuit package	K.D. Shim	93/8/18	P1 05749

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93-18223	Structure of heatsink for mounting in intergrated circuit package (Power Quad)	N.H. Kwak	93/9/10	P1 05745
93-22858	Loading and unloading apparatus of plating rack	S.Y. Park	93/10/30	P1 12771
93-25775	Semiconductor leadframe (Dambar supporting lead)	M.J. Lee	93/11/30	P1 22885
93-30799	Structure of leadframe pad (QFP, Tiebar Downset)	C.K. Park	93/12/30	U1 05970
93-31195	Method of eliminating flash for intergrated circuit package and structure of leadframe hereof (QFP, Tiebar Trim)	G. Lee	93/12/30	P1 09990
94-00395	Molding method and device of semiconductor package (MGP Mold)	G. Lee	94/1/12	P1 24549
94-01158	Method of manufacturing mold for semiconductor package and structure of mold thereof (Mold Tool)	G. Lee	94/1/22	P1 27190
94-01771	Method of manufacturing ink marking apparatus and structure of ink marking apparatus (Marking ad)	S.M. Choi	94/1/31	P1 27189
94-01772	Indexing method and apparatus in wire bonding process for semiconductor package	Y.G. Hwang	94/1/31	P1 13187
94-01774	Tiebar structure of leadframe (QFP)	G. LEE	94/1/31	P1 19059
94-02476	Ground terminal	C.B. LEE	94/2/8	U1 09467
94-03322	Method of recognizing leadframe in wire bonding process for semiconductor package (Pattern recognition system)	Y.G. Hwang	94/2/24	P1 21047



94-03494	Heatsink structure of thin package (PQ2)	S.D. Lee	94/2/25	P1 19650
94-03820	Heatsink structure (PQ2)	S.D. Lee	94/2/28	P1 24789
94-04109	Multi-magazine holder	H.Y. Lee	94/3/3	P1 26534
94-05635	Semiconductor leadframe (Oxide)	J.D. Kim	94/3/21	
94-05636	Semiconductor epoxy tool	S.K. Hwang	94/3/21	P1 21113
94-05852	Pick up tool of bonding semiconductor chip (Quad Type)	S.I. Kim	94/3/23	P1 22774
94-05967	Surface structure of heatsink for semiconductor package (PQ2)	S.D. Lee	94/3/24	P1 25999
94-06063	Structure of leadframe (Tiebar)	S.M. Seo	94/3/24	P1 26000
94-06064	Structure of heatsink for semiconductor package (PQ2: Making grooves at the center of heatsink)	S.D. Lee	94/3/25	P1 26001
94-06289	Pad structure of leadframe (Making holes at the center of paddle for preventing delamination rom paddle surface)	S.M. Seo	94/3/28	P1 19651
94-06290	Pad structure of leadframe (Making Down thickness at paddle as an etching method for free elamination)	S.M. Seo	94/3/28	P1 19652
94-06291	Pad structure of leadframe (consists of double paddle for reducing dimension)	S.M. Seo	94/3/28	P1 19653
94-06421	Leadframe structure (Free moisture)	S.M. Seo	94/3/29	U1 11266

94-06742	Tiebar of leadframe(Making holes in tiebar)	J.H. Ahn	94/3/31	P1 33014
94-06756	Mold of wire bonding for semiconductor package(Install subheater)	B.K. Han	94/3/31	
94-06775	Injection method of mold compound(Connect electric signal)	J.H. Ahn	94/3/31	P1 21114
94-06776	Structure of mold semiconductor package(Air vent)	G. Lee	94/3/31	P1 21112
94-08596	Heatsink feeding apparatus	G. Lee	94/4/22	P1 26529
94-08646	Leadframe of inspecting trimming and forming process (Identification mark)	K.C. Park	94/4/22	U1 08304
94-09056	Feeding apparatus for ink marking of intergrated circuit package	S.M. Choi	94/4/27	
94-09667	Font mask for LASER marking of intergrated circuit package	H.Y. Lee	94/5/2	U1 09734
94-10643	Copper heatspreader (Making embossed pattern on the central paddle)	T.H. Lee	94/5/16	P1 23424
94-10938	Leadframe (Making wave pattern in inner lead)	J.D. Kim	94/5/19	P1 23423
94-11454	Pot coupling structure of transfer apparatus	J.H. Choi	94/5/23	
94-11455	Transfer apparatus for molding semiconductor package	J.H. Choi	94/5/23	U1 16194
94-13647	Copper Oxide Filled polymer die attach adhesive composition for semiconductor package	C.W. Kwak	94/6/16	P1 24788

94-14332	Tape for preventing plating and method of plating semiconductor	N.H. Kwak	94/6/22	P1 26273
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	package			
94-15996	Relocation structure for cutting dambar	I.S. Kim	94/6/30	U1 14547
94-15772	Method and apparatus of ejecting semiconductor chip	J.H. Choi	94/7/1	P1 42152
94-15873	Method of reducing moisture and contamination penetration into microelectronics (Coating oxidation in leadframe)	J.D. Kim	94/7/2	P1 28165
94-16492	Transfer dual molding apparatus	J.H. Choi	94/7/8	
94-16948	Leadframe for plastic package (Coating silver in only wire bonding area)	C.K. Park	94/7/8	
94-18497	Heatsink projected out of semiconductor package	W.S. Shin	94/7/28	P1 56513
94-18498	Mold for molding semiconductor package	W.S. Shin	94/7/28	P1 56514
94-18499	Semiconductor package(Apply new type heatspreader)	W.S. Shin	94/7/28	P1 56515
94-19006	Heatsink projected out of semiconductor package	W.S. Shin	94/7/28	U1 09468
94-19290	Pad of leadframe(Cutting partly pad for free delamination)	D.H. Moon	94/8/4	P1 56516
94-21273	Package for test and method of manufacturing it	W.S. Shin	94/8/27	P1 44314

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94-21782	Method of molding and structure of mold(Dambarless)	G. Lee	94/8/31	P1 32702
94-23007	Leadframe of preventing leakage from solder and epoxy	D.H. Moon	94/9/7	U1 29005
94-22438	Method of manufacturing semiconductor package having heatsink (Solder material for preventing it from delamination and crack)	B.T. Dho	94/9/7	P1 37067
94-22439	Method and device of molding for intergrated circuit package (Dambarless)	G. Lee	94/9/7	P1 62887
94-22625	Method and device for molding of intergrated circuit package (Making a oxidatantlayer on heatspreader)	G. Lee	94/9/8	P1 42153
94-22626	Copper Oxide filled polymer die attach adhesive composition for semiconductor package	W.S. Shin	94/9/8	P1 44312
94-22712	Semiconductor package (Making embossed patterns as blocking epoxy wall)	L.H. Kim	94/9/9	P1 47420
94-23309	Semiconductor package (Making a grooved surface in paddle)	W.S. Shin	94/9/9	U1 33386
94-23663	A dry system for leadframe (Making a filtering apparatus in system)	N.H. Kwak	94/9/16	P1 49523
94-23431	A printing circuit board in semiconductor package (Making holes in PCB)	W.S. Shin	94/9/10	U1 20612
94-24279	Apparatus and method of elimination dummy dambar and dambar of semiconductor package	K.C. Park	94/9/27	P1 59304
94-25860	A method of adhesion of heatsink for semiconductor package	W.S. Shin	94/10/10	P1 47768

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94-25861	Leadframe (Connecting a plural of line pad & ground line pad)	W.S. Shin	94/10/10	P1 37068
94-26326	Leadframe (Making pattern for connecting signal, powerline and ground at the same time)	L.H. Kim	94/10/10	U1 29004
94-27230	Semiconductor package (Making connections directly from chip pad to PCB)	Y.W. Heo	94/10/25	P1 86961
94-28218	Method and apparatus of auto supply wafer	S.Y. Park	94/10/31	P1 37828
94-29045	Gate insert tip and tool used thereof	J.Y. Chung	94/11/2	U1 17395
94-30309	Driving apparatus of multi magazine for fabrication semiconductor equipment	W.H. Choi	94/11/16	U1 17628
94-30518	Apparatus of inspecting wire bonding of semiconductor package (Making controller in wire bonding machine)	K.B. Lee	94/11/19	P1 59967
94-30757	Leadframe (Making indentation mark in out lead)	W.Y. Pyo	94/11/21	U1 23589
94-31033	Die of forming machine and die tip thereof	K.H. Lee	94/11/23	U1 17412
94-31781	Method of adhesive semiconductor package on PCB (Connecting out lead on PCB as a solder ball)	J.K. Chun	94/11/29	

94-32145	Method of eject marking for die bonding and apparatus thereof (Making a circle of pattern on packaging surface)	Y.Y. Moon	94/11/30	P1 65765
94-32146	Ram apparatus of mold (Making respectively supporting ram parts)	Y.Y. Moon	94/11/30	P1 65764

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94-32642	Ejecting method for die bonding and apparatus thereof	C.W. Kwak	94/12/3	
94-32909	Automatic strip counter	K.D. Lee	94/12/6	
94-33257	Lifter(Making masspoint for carrying the objectives)	K.N. Bae	94/12/8	U1 09535
94-33288	Method of forming character and figure of tray(Easy to detach/Attach the character/Figure logo on tray surface)	I. Hang	94/12/8	
94-33423	Structure of hot plate for preheating leadframe (Making groove on hot plate)	B.T. Dho	94/12/9	U1 17452
94-33831	Magazine holder structure of leadframe loader	K.H. Lee	94/12/13	U1 12218
94-33832	Pusher structure of leadframe loader(Making the sensor for loading leadframe)	S.L. Park	94/12/13	U1 29225
94-33833	Pusher apparatus of leadframe loader (Making air-cylinder for loading leadframe)	W.H. Kung	94/12/13	U1 29221
94-33834	Leadframe heater block stracture (Making embossed pattern and fixed gripper heater block)	K.H. Lee	94/12/13	U1 17717
94-33835	Semiconductor package (Connecting a plural of signals for integrated circuit package)	I.K. Park	94/12/13	U1 17716
94-33931	Gripper apparatus of leadframe loader for semiconductor package	W.H. Kung	94/12/13	P1 38057
94-33932	Feeding loader apparatus of leadframe loader for semiconductor package	S.L. Park	94/12/13	P1 38055
94-33933	Leadframe loader system for semiconductor package	K.H. Lee	94/12/13	P1 27628

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94-33934	Magazine holder of leadframe loader for semiconductor package	W.H. Kung	94/12/13	P1 27618
94-33935	Robot apparatus of leadframe loader for semiconductor package	M.H. Park	94/12/13	P1 27619
94-33936	Heater block apparatus of leadframe loader for semiconductor package	K.H. Lee	94/12/13	P1 38054
94-33993	Pad structure of semiconductor package (Making a plural of heat dissipation shapes)	B.H. Ahn	94/12/14	
94-34165	Leadframe for manufacturing semiconductor package (Preventing wire shorting)	D.H. Park	94/12/14	P1 40458
94-34170	Heater block of wire bonding for semiconductor package (Making a plural of embossed pattern on paddle for preventing crack & distortion)	Y.S. Jung	94/12/14	P1 38056
94-34332	Heatsink for semiconductor package (Making a circle grooved pattern on heatsink)	W.S. Shin	94/12/16	U1 34092
94-34333	Heatsink for semiconductor package (Making a variety of heatsink for heat dissipation)	K.S. Jung	94/12/16	
94-34334	Structure of leadframe (Making slots on pad for preventing thermal distortion)	S.B. Kwak	94/12/16	
94-34664	Structure of leadframe for manufacturing semiconductor package (Making a variety of pattern for combining molding resin)	K.S. Jung	94/12/16	
94-34809	Heater block for wirebonding (Making different steps on heater block)	J.H. Jo	94/12/17	P1 79472
94-35635	Structure of leadframe for semiconductor package (Making specific dambar pattern)	G. Lee	94/12/21	P1 70022

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94-35636	Device and method of molding semiconductor (Dambarless)	G. Lee	94/12/21	P1 72188
94-35637	Device and method of molding semiconductor (Making a plural of gates for same pressure on molding process)	I.T. Han	94/12/21	P1 43021
94-35246	Apparatus of eliminating particle of apparatus for manufacturing semiconductor package (Making air blower on trim/form appratus)	K.H. Lee	94/12/23	U1 33388
94-35247	Cam floater of equipment for fabricating semiconductor package	Y.H. Choi	94/12/23	U1 17627
94-35248	Stroker of floating bar and index for fabricating semiconductor equipment	K.H. Lee	94/12/23	U1 19164
94-35249	Adjusting apparatus of finger pin position for fabricating semiconductor equipment	K.H. Lee	94/12/23	
94-35250	Detecting apparatus for setting position of leadframe	K.H. Lee	94/12/23	
94-35251	Spanking apparatus for fabricating semiconductor equipment	K.H. Lee	94/12/23	U1 17800
94-35252	Double forming apparatus for fabricating semiconductor equipment	K.H. Lee	94/12/23	U1 23314
94-35253	Detecting apparatus of mis-alignment package for fabricating semiconductor equipment	K.H. Lee	94/12/23	U1 17626
94-35254	Semiconductor package guide in semiconductor equipment	K.H. Lee	94/12/23	U1 27109
94-35255	Feeding apparatus of semiconductor package	K.H. Lee	94/12/23	U1 26333
94-35256	Degating apparatus	Y.S. Kim	94/12/23	U1 20491

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94-35257	Burr pressing apparatus	Y.S. Kim	94/12/23	U1 32461
94-35258	Detecting apparatus of mis-loading tube for fabricating semiconductor equipment	Y.H. Choi	94/12/23	U1 20490
94-35259	Inserting apparatus of package into tube	K.H. Lee	94/12/23	U1 18231
94-36206	Forming machine	Y.M. Choi	94/12/23	P1 38840
94-36207	Apparatus of operating slope cam	Y.S. Kim	94/12/23	P1 27785
94-36208	Tubular feeding method	K.H. Lee	94/12/23	P1 37814
94-36219	Method of coating in semiconductor chip	K.H. Lee	94/12/23	P1 67143
94-36220	Coating apparatus for semiconductor package	K.H. Lee	94/12/23	P1 67142
94-36221	Loader of feeding for coating equipment	K.H. Lee	94/12/23	P1 43020
94-36222	Coating machine for semiconductor package	M.I. Kim	94/12/23	P1 67144
94-36223	Machine of coating for semiconductor package	M.I. Kim	94/12/23	P1 84714
94-36224	Method of operating coating system	M.I. Kim	94/12/23	P1 39266

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94-37167	Method of marking semiconductor package	L.H. Kim	94/12/27	
94-37168	Leadframe pad structure (Making x-type paddle for reducing paddle dimension)	I.K. Han	94/12/27	P0 201062
94-38872	Structure of molding for semiconductor package (Making chamfer type on the edge of siderail)	Y.Y. Moon	94/12/29	P1 67145
94-39354	Semiconductor package (Consists of metal cap and advanced adhesive)	Y.W. Heo	94/12/30	P1 67141
95-00812	Jig of inspecting semiconductor package	S.Y. Lee	95/1/20	
95-00940	Supporting trim die for leadframe	I.S. Kim	95/1/20	P1 43139

95-01928	Apparatus of lead sparking for semiconductor package	I.S. Kim	95/2/3	P1 43138
95-06328	Structure of feeding belt for equipment of manufacturing semiconductor package	B.H. Park	95/3/31	U1 29220
95-06329	Apparatus of seperading bottom module	B.H. Park	95/3/31	U1 20549
95-07361	Transfer molding apparatus	S.I. Kim	95/3/31	P1 72052
95-07362	Method and device for forming the lead of PLCC semiconductor package	B.H. Park	95/3/31	P1 72051
95-07363	Semiconductor leadframe	D.M. Moon	95/3/31	
95-09198	Semiconductor package (Connecting between chip and heatsink as PCB)	J.H. Ku	95/4/19	

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95-10418	Method for leveling solder ball array in BGA semiconductor package	Y.W. Heo	95/4/29	P1 79473
95-15045	A device for heating periphery of semiconductor mold die	C.S. Yoo	95/6/8	P1 45996
95-16397	Device for loading leadframe and heatspreader	J.Y. Chung	95/6/20	
95-19581	Method and circuit board structure for leveling solder ball in BGA semiconductor package			
95-19582	BGA semiconductor package with improved heat dissipation and dehumidification	I.K. Shim	95/7/5	P1 59987
95-19583	Structure of heatsink for semiconductor package (Including Ni & Pd layer for wire bonding easily)	W.S. Shin	95/7/5	P1 59985
95-19584	Method of manufacturing semiconductor package (Using solder plating and solder reflow)	W.S. Shin	95/7/5	P0 192226
95-21041	Pad structure of leadframe	I.K. Han	95/8/16	
95-21042	Leadframe structure (Making the paddle surface like net)	D.H. Park	95/8/16	
95-21043	Heatsink structure (Making groove on heatsink's surface)	S.M. Kim	95/8/16	
95-21044	Identifying mark for P.W.B. strip	Y.M. Kim	95/8/16	
95-25172	Thin BGA semiconductor package with exposed heatsink	I.K. Shim	95/8/16	P1 86759
95-23884	Structure of semiconductor package (Attaching lead heatsink on lead surface)	W.S. Shin	95/9/4	
95-28770	Auxiliary oil pressure apparatus of mold press for manufacturing semiconductor package	M.S. Lee	95/9/4	

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95-28772	Bonding method for the semiconductor chips	S.J. Jang	95/9/4	P1 86752
95-24350	Device of intergrated circuit and method thereof	Rorert	95/8/7	
95-29420	Identifying mark for P.W.B. strip	C.K. Park	95/10/19	U1 43923
95-29421	Heatsink structure for semiconductor package (Making groove on the below of heatsink)	C.H. Woo	95/10/19	
95-29422	Heatsink structure for semiconductor package	J.H. Koo	95/10/19	
95-29423	Heatsink structure for semiconductor package (Making groove at dambar/tiebar)	D.B. Kang	95/10/19	
95-36139	Semiconductor package strip (Forming the rectangular of holes in trim/form process for identifying mark)	D.J. Bae	95/10/19	
95-36140	Semiconductor L.O.C. package structure	S.G. Lee	95/10/19	
95-36141	PCB manufacturing method and BGA semiconductor package structure of the same	D.J. Bae	95/10/19	
95-36142	Tube vibrating device of semiconductor manufacturing equipment	B.S. Bae	95/10/19	
95-36143	Leadframe of semiconductor package (Making notch for preventing distortion before trim/form process)	G. Lee	95/10/19	
95-36144	Marking method of semiconductor package	W.S. Shin	95/10/19	
95-36145	Mold die for manufacturing semiconductor package	L.H. Kim	95/10/19	
95-30143	Heater block structure for wire bonding	J.M. Kim	95/10/25	
95-30144	Heater block structure for wire bonding	D.S. Sho	95/10/25	

95-30145	Dispensing system for die coating	B.H. Moon	95/10/25	
95-36947	Solder ball forming method of BGA semiconductor package	I.K. Shim	95/10/25	
95-36948	M.C.M. package	C.K. Park	95/10/25	
95-36949	Magazine fixing device of trim/forming apparatus for manufacturing semiconductor package	B.H. Park	95/10/25	P1 66561
95-36950	Heatsink structure of semiconductor package (Making holes on heatsink)	J.H. Yun	95/10/25	P0 201063
95-37513	Printed circuit board having epoxy barrier around its throughout slot and ball grid array semiconductor package using such a printed circuit board, thereby exhibiting a high moisture discharge characteristic	Y.W. Heo	95/10/27	P1 70024
95-33139	Forming punch of manufacturing equipment for semiconductor package	M.S. Moon	95/11/11	
95-33140	Trim die fixing holder of manufacturing equipment for semiconductor package	M.S. Moon	95/11/11	
95-40842	Automatic speed checking apparatus of transfer ram in mold press of semiconductor manufacturing equipment	TY JUNG	95/11/11	
95-40843	Semiconductor package forming method	M.S. Moon	95/11/11	
95-33944	Supply device of semiconductor package inserted into the tube	K.H. Lee	95/11/16	
95-33945	Semiconductor package lead fixing device	K.H. Lee	95/11/16	
95-33946	Detecting device for bad tube	K.H. Lee	95/11/16	
95-33947	Supply device of semiconductor package tube	W.H. Choi	95/11/16	

95-33948	Marking structure in semiconductor package marking equipment	W.H. Choi	95/11/16	
95-41665	Semiconductor package test equipment	W.H. Choi	95/11/16	P1 71668
95-41843	Semiconductor package leadframe manufacturing method and semiconductor package manufacturing process/structure thereof	W.S. Shin	95/11/17	P0 198313
95-41844	Semiconductor package structure (Making a variety of chemicals layer for adhesive power)	W.S. Shin	95/11/17	
95-41845	Semiconductor chip bonding method and structure for using solder ball	J.K. Lee	95/11/17	P0 201379
95-41846	Using printed circuit board carrier frame for ball grid array semiconductor package and method for fabricating ball grid array semiconductor package using the same			
95-34640	Epoxy mixing apparatus (Using irregular vibration)	D.Y. Sho	95/11/21	
95-34641	Absorption block of semiconductor package manufacturing method of the same	D.Y. Sho	95/11/21	
95-42560	Method and structure for manufacturing heatsink of semiconductor package (Using the method of casting & sintering)	W.S. Shin	95/11/21	
95-36372	Capillary of bonding device for manufacturing semiconductor package	J.H. Choi	95/11/29	
95-36373	Heatspread safe mounter for semiconductor package	D.S. Kim	95/11/29	
95-44553	Method and structure for manufacturing semiconductor package (CSP)	W.S. Shin	95/11/29	P1 80280
95-47009	Method and structure for manufacturing semiconductor package (CSP)	I.T. Han	95/12/6	P1 78626

95-38947	Solder ball forming method for BGA semiconductor package			
95-38855	Leadframe fixing apparatus for semiconductor package	I.S. Hwang	95/12/7	
95-47349	Solder ball safe mounting device in integrated circuit package	I.S. Hwang	95/12/7	P1 80281
95-45942	Heater block of apparatus for manufacturing semiconductor package	S.J. Son	95/12/22	
95-48972	Leadframe structure for semiconductor package (Reducing the dimension between paddle and lead)	S.G. Lee	95/12/27	U0 143373
95-48973	Pad structure of leadframe (Making spiral shape on leadframe)	D.H. Moon	95/12/27	
95-48974	Pad structure of leadframe	I.K. Han	95/12/27	
95-58806	Semiconductor package leadframe with stress absorbing means on fused leads	Y.S. Jung	95/12/27	P1 91078
95-58807	Semiconductor package using flip chip technique (CSP)	D.S. Yoo	95/12/27	
95-58808	Frame structure for cleaning mold die (Anodizing metalliclayer or metallic tape)	D.S. Kim	95/12/27	
95-58809	Chip size semiconductor package (CSP using substrate attaching anisotropic conductive film and copper foil)	S.G. Lee	95/12/27	
95-50614	Semiconductor package (Making dam for preventing delamination from the top & bottom of paddle)	W.S. Shin	95/12/28	
95-50615	Structure of semiconductor package (Paddleless)	D.H. Moon	95/12/28	
95-50616	Semiconductor package (Surrounded by metal-cap at the bottom)	S.M. Kim	95/12/28	
95-50617	Leadframe structure for semiconductor packaging having fused area	E.S. Son	95/12/28	

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95-50618	Leadframe structure for semiconductor packaging (Making slots on lead tip for reducing thermal stress)	E.S. Son	95/12/28	
95-50619	Structure of semiconductor package (Attaching the reliable heatsink)	J.H. Yoon	95/12/28	
95-50620	Plug of tube for shipping semiconductor package (Making a versatile plug)	I. Hwang	95/12/28	
95-61438	Semiconductor package (Making dam for sweeping molding compound)	M.Y. Lee	95/12/28	P1 91076
95-61439	Structure of heat slug for semiconductor package (Making wings on the peripheral heat plug for gaining locking power)	J.H. Ku	95/12/28	P1 91077
95-61440	Method of manufacturing leadframe (Adding thermal process in forming process)	W.S. Shin	95/12/28	
95-52621	Leadframe structure for semiconductor package (Making tiebar for preventing chip out from chip paddle)	K.J. Kim	95/12/29	
95-52622	Leadframe structure for semiconductor package (Making a lot of leads for integrated circuit)	Y.C. Lyu	95/12/29	
95-52623	Method for supplying electricity of rectifier during plating process by iron plating	A.K. Kang	95/12/29	
95-52624	Device for detecting fixed state of leadframe during plating process by iron plating (Attaching the touch sensor at the below of Iron plating belt)	C.K. Kim	95/12/29	
95-52625	Structure for preventing grip belt from sagging during plating process by iron plating	A.K. Kang	95/12/29	
95-52626	Filtering method of plating liquid in plating process	A.K. Kang	95/12/29	

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95-53421	Pellet kicker structure for manufacturing semiconductor package	Y.J. Kwun	95/12/29	
95-53422	Molding apparatus for cutting flash of thin semiconductor package	Y.J. Kwun	95/12/29	
95-53423	Ink marking area structure of heatsink for semiconductor package	L.H. Kim	95/12/29	
95-53424	Structure of semiconductor package for preventing leakage of electromagnetic wave	D.H. Park	95/12/29	
95-53425	Method of manufacturing chip size semiconductor package	Y.S. Yoon	95/12/29	

95-53426	Tray for semiconductor package (Making supporting pole at the side of tray)	I. Hwang	95/12/29
95-53427	Heatsink structure for semiconductor package (Making cap type)	S.G. Lee	95/12/29
95-53428	Heatsink structure for semiconductor package (Making a lot of stripe on heatsink)	D.B. Kang	95/12/29
95-53429	Structure of installing pad of cam punch for forming semiconductor package	H.Y. Lee	95/12/29
95-53430	Structure of controlling position of cam punch for forming semiconductor package	H.Y. Lee	95/12/29
95-53431	Apparatus of operating cam punch for forming semiconductor package	H.Y. Lee	95/12/29
95-53432	Structure of cam punch for forming semiconductor package	H.Y. Lee	95/12/29
95-53433	Structure of cleaning pad for marking semiconductor package	H.Y. Moon	95/12/29
95-53434	Structure of semiconductor package (tiebarless & downset less)	D.S. Yoo	95/12/29
95-65450	Semiconductor package (CSP: connecting between chip pad and bond pad as a gold ball)	D.H. Park	95/12/29

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95-65451	Structure of semiconductor package (CSP)	S.M. Kim	95/12/29
95-65452	Structure of semiconductor package (Trim-less)	S.M. Kim	95/12/29
95-65453	Method of coating surface of semiconductor package	B.H. Ahn	95/12/29
95-67199	Cam die for forming semiconductor package	H.Y. Lee	95/12/29
95-67200	Mold die for molding semiconductor package	D.J. Kim	95/12/29
95-67201	Cam punch for forming semiconductor package	H.Y. Lee	95/12/29
95-67202	Method of adhesive semiconductor chip and structure of leadframe (QFP)	Y.K. Lee	95/12/29
95-67203	Structure of leadframe and method of attaching semiconductor package using	Y.J. Park	95/12/29
95-67204	Die of cutting lead	J.Y. No	95/12/29
95-67205	Punch of cutting lead	I.K. Ko	95/12/29
95-55056	Storage box of die-bonded leadframe materials	M.S. Park	95/12/30
95-55057	Storage box for leadframe stacked magazine during manufacturing package	H.L. Kim	95/12/30
95-55058	Block letter pad attaching structure of marking equipment for manufacturing semiconductor package	B.H. Park	95/12/30
95-55059	Semiconductor package (Making holes on PKG-body for controlling loading position)	D.J. Bae	95/12/30
95-55060	Bend reforming device in PCB frame materials	Y.S. Hwang	95/12/30
95-69090	Flux spreading method of integrated circuit package	Y.S. Hwang	95/12/30

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95-69091	Block letter plate fixing device of marking apparatus for manufacturing semiconductor package	B.H. Park	95/12/30
95-69092	Marking apparatus for manufacturing semiconductor package	B.H. Park	95/12/30
95-69093	Semiconductor package for using solderballs and leads as I/O terminal	Y.S. Son	95/12/30
95-69094	Chip size package structure and manufacturing method thereof	S.H. Ha	95/12/30
95-69095	Chip size package and manufacturing method thereof	S.H. Ha	95/12/30
95-69096	Chip size package structure and manufacturing method thereof	S.H. Ha	95/12/30
95-69097	Chip size package	K.C. Lee	95/12/30
95-69098	BGA semiconductor package	N.H. Kwak	95/12/30
95-69099	Leadframe of semiconductor package (Making double ring for wire bonding easily power bonding and ground bonding)	S.D. Lee	95/12/30



95-69100	Package heating method during wire bonding process of manufacturing semiconductor package	B.H. Moon	95/12/30	
95-69101	Semiconductor package (CSP)	Y.M. Kim	95/12/30	
96-05342	Die bonder	C.J. Song	96/2/29	P0189378
96-05343	Wafer map conversion method	C.J. Song	96/2/29	P0192216
96-05345	Method of producing BGA semiconductor package metal carrier frame and BGA package produced by such method	I.K. Shim	96/2/29	P0192760

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96-06302	Method of manufacturing semiconductor package and structure produced by such method (CSP: Making solder bump on chip pad)	Y.W. Heo	96/3/11	P0192758
96-06303	Method of forming bump of CSP package (Forming bump on chip pad)	Y.W. Heo	96/3/11	P0192759
96-09774	Method of manufacturing semiconductor package and structure produced by such method	Y.W. Heo	96/4/1	
96-09775	Semiconductor package and method of manufacturing the same (BLP)	W.S. Shin	96/4/1	
96-09777	BGA semiconductor package	M.E. Lee	96/4/1	
96-09778	Solder ball land metal structure of BGA semiconductor package	M.E. Lee	96/4/1	
96-06892	Structure for connecting mold chase of mold for manufacturing semiconductor package	H.J. Lee	96/4/1	U0146456
96-14883	Apparatus for changing fixture of UV03 automatic cleaner	K.N. Kim	96/6/4	U0148893
96-14884	Apparatus for controlling width of guide rail in leadframe loader	Y.C. Cho	96/6/4	
96-14885	Leadframe loader	K.N. Kim	96/6/4	
96-14886	Handler apparatus of UV03 automatic cleaner	Y.C. Cho	96/6/4	U0148894
96-19858	Fixture structure of UV03 automatic cleaner	K.N. Kim	96/6/4	
96-19859	Loading and unloading apparatus of UV03 automatic cleaner	Y.C. Cho	96/6/4	
96-19860	UV03 automatic cleaner apparatus	K.N. Kim	96/6/4	
96-16791	Structure of heater block for bonding wire for BGA semiconductor package	I.S. Yoon	96/6/20	

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96-16792	Mold structure for molding BGA semiconductor package	I.S. Yoon	96/6/20	
96-16793	Heatsink for semiconductor package	B.H. Ahn	96/6/20	
96-22659	Leadframe structure and method of manufacturing semiconductor package using the same (Making supporting poles near by tiebar)	S.K. Lee	96/6/20	
96-22660	Leadframe pad of semiconductor package for improving molding reliability (Making a plural of adhesive pattern at the peripheral of paddle)	K.O. Sohn	96/6/20	
96-22661	Leadframe pad of semiconductor package for improving molding reliability	K.O. Sohn	96/6/20	
96-22897	Array chip scale semiconductor package	W.S. Shin	96/6/21	
96-22898	Array chip on chip semiconductor package	I.K. Han	96/6/21	
96-22899	Lead array leadframe and semiconductor package using the same	B.J. Han	96/6/21	
96-22900	Semiconductor package and method of manufacturing the same (paddleless and tiebarless)	L.H. Kim	96/6/21	
96-22901	Semiconductor package and method for fabrication the same (CSP)	Y.W. Heo	96/6/21	
96-22902	Leadframe structure and semiconductor package using the same (Downset-less)	B.H. Ahn	96/6/21	P0198312
96-22903	Method of molding BGA semiconductor attached heatsink	Y.M. Kim	96/6/21	
96-27617	Structure of socket for BGA semiconductor package	J.H. Yoon	96/7/9	
96-27618	Leadframe structure and semiconductor package using the same (QFP)	J.H. Yoon	96/7/9	

96-27619	Purity supply system for building wafer	Y.W. Kim	96/7/9	
96-29000	Tray for inspecting reliability of semiconductor package	H.S. Jang	96/7/18	
96-29001	Apparatus of inspecting reliability of semiconductor package	H.S. Jang	96/7/18	P182191
96-21510	Structure of megazine	B.T. Hwang	96/7/22	
96-21511	Ion plating apparatus for semiconductor package	A.K. Kang	96/7/22	U0149178
96-21512	Apparatus of inserting semiconductor package	B.H. Park	96/7/22	
96-21513	Loading apparatus of leadframe in ion plating process	A.K. Kang	96/7/22	U0146267
96-29555	Automatic solder ball placement apparatus	D.S. Cho	96/7/22	
96-29556	Apparatus of loading PCB of automatic solder ball placement system	J.L. Jang	96/7/22	
96-29557	Apparatus of vibrating solder ball mounting members of automatic solder ball placement system	D.S. Cho	96/7/22	
96-29558	Robot arm apparatus of automatic solder ball placement system	J.Y. Ha	96/7/22	
96-29559	Apparatus of transferring leadframe of making apparatus for manufacturing semiconductor package	B.H. Park	96/7/22	
96-30286	Air blow system for semiconductor package	Y.I. Jang	96/7/25	P0201378
96-30287	Apparatus for reloading of automatic solder ball placement system	B.P. Jung	96/7/25	
96-30486	Structure of establishing circuit position of mold for semiconductor package	Y.Y. Moon	96/9/21	U145718

96-41463	Heatspreader structure (PQIP)	S.K. Lee	96/9/21	
96-41464	Stacking BGA semiconductor package	S.M. Kim	96/9/21	
96-41465	Circuit board for BGA semiconductor package for testing electric reliability	Y.M. Kim	96/9/21	
96-41466	Apparatus of testing electric reliability for semiconductor package (Making prove pin on PCB)	Y.M. Kim	96/9/21	
96-41467	Heatspreader for semiconductor package	D.Y. Kim	96/9/21	P187801
96-41468	Semiconductor package structure	D.H. Park	96/9/21	P196493
96-41470	Mold for BGA semiconductor package	Y.Y. Moon	96/9/21	P194362
96-41472	PCB clamping apparatus for molding BGA semiconductor package	Y.Y. Moon	96/9/21	P196494
96-43841	CSP structure and method of manufacturing the same	Y.Y. Moon	96/10/4	
96-43842	CSP structure and method of manufacturing the same	S.K. Lee	96/10/4	
96-43844	BGA semiconductor package	S.K. Lee	96/10/4	
96-44452	3th form die holder of trim and form system	S.K. Lee	96/10/7	P0207341
96-44453	Singulation die holder of trim and form system	J.B. Kim	96/10/7	P0207342

96-44454	Form die holder of trim and form system	M.H. Park	96/10/7	P189395
96-44789	Heatsink-integrated semiconductor package with double encapsulating parts and method for fabricating the same	W.S. Shin	96/10/9	
96-46656	Semiconductor package	S.K. Lee	96/10/18	

96-46657	Semiconductor package	S.K. Lee	96/10/18
96-34290	Wire spool structure of wire bonding apparatus	S.H. Kim	96/10/18
96-46948	PCB strip structure and semiconductor package produced by such method		
96-46949	CSP semiconductor package and method of manufacturing the same	S.K. Lee	96/10/19
96-47915	Solder bumping apparatus	K.H. Lee	96/10/24
96-47916	Apparatus of transferring BGA semiconductor package of solder bumping apparatus	K.H. Lee	96/10/24
96-47917	Solder ball mounting apparatus of solder bumping apparatus	K.H. Lee	96/10/24
96-47918	Solder tray apparatus of solder bumping apparatus	K.H. Lee	96/10/24
96-47919	Apparatus of inspecting adhesion status of solder bumping apparatus	K.H. Lee	96/10/24
96-47920	Solder ball unloading apparatus of solder bumping apparatus	K.H. Lee	96/10/24
96-47921	Apparatus of inspecting solder ball mounting of solder bumping apparatus	K.H. Lee	96/10/24
96-47922	Loading apparatus of solder bumping apparatus	K.H. Lee	96/10/24

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96-49378	Mold for semiconductor package	H.Y. Yoo	96/10/29
96-49379	Semiconductor package (Making at least one of the via-hole at the bottom in molding process)	H.Y. Yoo	96/10/29
96-51528	Leadframe for semiconductor package	Y.S. Jung	96/11/1
96-58753	Method of manufacturing leadframe having exposed and arrayed I/O terminal at below surface of semiconductor package(CSP)	W.S. Shin	96/11/28
96-58754	Method of manufacturing leadframe having fused solder ball at below surface of semiconductor package(CSP)	W.S. Shin	96/11/28
96-58755	Semiconductor package structure(TQFP)	W.S. Shin	96/11/28
96-58756	CSP structure having bottom lead type	W.S. Shin	96/11/28
96-58757	Leadframe structure for CSP	S.S. Jang	96/11/28
96-58758	Method of forming flip chip bump	J.H. Song	96/11/28
96-58759	Lead on chip area array bumped semiconductor package	W.S. Shin	96/11/28
96-58760	Area array bumped semiconductor package having ground and power lines	W.S. Shin	96/11/28
96-58761	Area array bumped semiconductor package having a plurality of chips	W.S. Shin	96/11/28
96-58762	Area array bumped semiconductor package having ground and power lines	W.S. Shin	96/11/28
96-58800	Wafer transfer apparatus of wafer mounting system	W.H. Kong	96/11/28
96-58801	Alignment of wafer mounting system	C.B. Lee	96/11/28 P199821

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96-58802	Chuck apparatus of wafer mounting system	W.H. Kong	96/11/28	P199822
96-58803	Wafer check of wafer mounting system	W.H. Kong	96/11/28	P199823
96-58804	Frame check of wafer mounting system	W.H. Kong	96/11/28	P199824
96-58805	Apparatus of cutting tape of wafer mounting system	W.H. Kong	96/11/28	P199825
96-58806	Roller apparatus of wafer mounting system	C.B. Lee	96/11/28	P199826
96-58807	Tape transfer apparatus of wafer mounting system	W.H. Kong	96/11/28	P199827
96-58808	Tape tension main tenance detaining of wafer mounting system	W.H. Kong	96/11/28	
96-58809	Station of wafer mounting system	W.H. Kong	96/11/28	
96-58810	Liner of mold for semiconductor package	Y.Y. Moon	96/11/28	
96-58811	Loading bar of mold for semiconductor package	Y.Y. Moon	96/11/28	

96-58812	PCB of BGA semiconductor package	Y.Y. Moon	96/11/28	
96-58813	PCB of BGA semiconductor package	Y.Y. Moon	96/11/28	
96-58814	PCB transferring apparatus of forming system for BGA semiconductor package	Y.Y. Moon	96/11/28	
96-58815	Cavity plating installation structure of molding device for BGA semiconductor package	Y.Y. Moon	96/11/28	P198031

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96-58816	Top molding structure of molding device for BGA semiconductor package	Y.Y. Moon	96/11/28	P198032
96-58817	Wafer mounting method and apparatus for semiconductor package	C.B. Lee	96/11/28	
96-61958	Trimming method and apparatus for semiconductor package	HJ Son	96/12/5	
96-61959	Apparatus for inspecting trag inner material	C.H. Lee	96/12/5	
96-62298	Structure and manufacturing method of CSP	I.T. Han	96/12/6	
96-62299	Structure and manufacturing method of CSP	I.T. Han	96/12/6	
96-62300	BGA semiconductor package	W.Y. Pyo	96/12/6	
96-62301	Semiconductor package	K.C. Lee	96/12/6	
96-62302	BGA semiconductor package	W.Y. Pyo	96/12/6	
96-62303	Structure preventing bending effect from semiconductor package	T.B. Jung	96/12/6	
96-62304	Structure and manufacturing method of CSP	I.T. Han	96/12/6	
96-62305	Method for marking poor quality printed circuit board units of printed circuit board strip for semiconductor package and the printed board strip			
96-62307	The Structure of semiconductor package(The dual type of BGA package)	W.S. Shin	96/12/6	
96-62308	The Structure of semiconductor package(Stacking chip on leadframe)	W.S. Shin	96/12/6	
96-62309	The molding method of semiconductor package	W.S. Shin	96/12/6	
96-62310	Structure of semiconductor package with good heat dissipation	W.S. Shin	96/12/6	

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96-62311	Cleaning method of die	B.H. Moon	96/12/6	
96-62312	Manufacturing method of leadframe and CSP using the same	W.S. Shin	96/12/6	
96-62313	The structure and manufacturing method of CSP	W.S. Shin	96/12/6	
96-62314	The structure of leadframe and semiconductor package using the same	I.S. Yoon	96/12/6	
96-62315	The structure of leadframe for semiconductor package	S.M. Seo	96/12/6	
96-62316	Bond-pad structure of semiconductor chip	J.H. Song	96/12/6	
96-62317	Lead-finger structure of flip-chip board	S.M. Seo	96/12/6	
96-62318	The structure of flip-chip board	J.H. Song	96/12/6	
96-65236	Structure and method of BGA semiconductor package with heatsink	I.K. Shim	96/12/13	
96-65237	Semiconductor package	S.K. Lee	96/12/13	
96-68819	Nonfunctional metal in clamping area	Y.M. Kim	96/12/20	
96-68820	Structure and manufacturing method of semiconductor package (Installing luminous diode in chip for malfunction test)	J.H. Yoon	96/12/20	
96-74111	The structure of leadframe and semiconductor package using the same	J.H. Yoon	96/12/27	
96-74112	Structure and manufacturing method of CSP with pin grid array	J.H. Yoon	96/12/27	
96-74113	Structure and manufacturing method of semiconductor package	J.H. Yoon	96/12/27	
96-74114	Structure and manufacturing method of semiconductor package	J.H. Yoon	96/12/27	

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96-74115	Structure and manufacturing method of semiconductor package (Attaching internally double chip on leadframe)	J.H. Yoon	96/12/27
96-74116	The solderball land of PCB for semiconductor package	M.E. Lee	96/12/27
96-74117	The structure of PCB for BGA semiconductor package	Y.W. Heo	96/12/27
96-74118	Attaching apparatus of solderball for integrated circuit package	Y.W. Heo	96/12/27
96-74119	The structure of semiconductor package	D.B. Kang	96/12/27
96-64037	Heatspreader for semiconductor package	L.H. Kim	96/12/30
96-77898	BGA semiconductor package built-in carrier frame	I.K. Shim	96/12/30
96-77899	BGA semiconductor package with carrier frame	I.K. Shim	96/12/30
96-77900	Flexible circuit board of die flag for BGA semiconductor package	I.K. Shim	96/12/30
96-77901	Flexible circuit board of die flag for BGA semiconductor package	Y.W. Heo	96/12/30
96-77902	Flexible circuit board of die flag for BGA semiconductor package	Y.W. Heo	96/12/30
96-77903	Molding apparatus for area array bumped semiconductor package	W.S. Shin	96/12/30
96-77904	The structure of leadframe paddle	D.H. Moon	96/12/30
96-77905	Apparatus dispensing epoxy for semiconductor package	D.H. Moon	96/12/30
96-77906	Apparatus dispensing epoxy for semiconductor package	W.S. Shin	96/12/30
96-77907	The structure of leadframe	J.J. Lee	96/12/30
96-77908	Plasma cleaner for semiconductor apparatus	S.H. Ha	96/12/30

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96-77909	Plasma cleaner for semiconductor apparatus		
96-77915	Attaching method and structure for semiconductor package	M.H. Park	96/12/30
96-77916	Printed circuit board for BGA semiconductor package	J.H. Ku	96/12/30
96-77917	The structure of non conductive surface for semiconductor package	J.Y. Chung	96/12/30
96-77918	Semiconductor package	J.Y. Chung	96/12/30
96-77919	Leadframe for semiconductor package	J.H. Cho	96/12/30 P199829
96-77920	Printed circuit board for BGA semiconductor package	L.H. Kim	96/12/30
96-77921	The apparatus of die-bonding	B.S. Kim	96/12/30 P0206515
96-77922	Printed circuit board for BGA semiconductor package	Y.M. Kim	96/12/30
96-77923	Back-end auto-inspection system for BGA semiconductor package	K.H. Lee	96/12/30
96-77924	The apparatus providing PCB in back-end auto inspection system	K.H. Lee	96/12/30
96-77925	PCB guide in back-end auto inspection system	K.H. Lee	96/12/30
96-77926	Inspection apparatus in back-end auto-inspection system	K.H. Lee	96/12/30
96-77927	The apparatus transferring PCB in back-end auto-inspection system	S.H. Jang	96/12/30
96-77928	The apparatus outleting PCB in back-end auto-inspection system	K.H. Lee	96/12/30
96-77929	Turn-guide of PCB in back-end auto-inspection system	K.H. Lee	96/12/30

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96-77930	Grip apparatus of PCB in back-end auto-inspection system	K.H. Lee	96/12/30
96-77931	The structure of PCB for BGA semiconductor package	S.M. Kim	96/12/30

96-77932	The enlarged scale semiconductor package	J.Y. Chung	96/12/30
96-77933	Structure and method of heatspreader coating surface	L.H. Kim	96/12/30
97-01592	Structure and method of CSP	I.K. Shim	97/1/21
97-02504	The sigulation method of BGA semiconductor package	Y.W. Heo	97/1/28
97-02259	Magazine (Making safely stacked guide ring)	B.S. Park	97/2/14
97-04432	Semiconductor package (PGA)	Y.S. Sohn	97/2/14
97-04433	Semiconductor package (Using the pin-type of metal sheet)	Y.S. Sohn	97/2/14
97-04434	The marking method of semiconductor package	Y.S. Sohn	97/2/14
97-04435	The method of forming solder-ball land and BGA semiconductor package including the same	S.J. Kim	97/2/14
97-04436	The mounting method of semiconductor package	K.C. Lee	97/2/14
97-02323	The structure of printed circuit board	Y.M. Kim	97/2/17
97-04652	Structure and manufacturing method for flip-chip semiconductor package	S.J. Kim	97/2/17
97-04653	BGA semiconductor package	W.Y. Pyo	97/2/17
97-04654	Metallic semiconductor package (CSP)	Y.M. Kim	97/2/17
97-04655	Structure and manufacturing method of CSP	Y.M. Kim	97/2/17

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97-04657	Ball grid array semiconductor package	S.S. Cha	97/2/17
97-04870	CSP semiconductor package using flexible circuit board	I.K. Shim	97/2/18
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97-06062	The structure of semiconductor package	Y.W. Heo	97/2/26
97-06063	Structure and manufacturing method of semiconductor package (CSP)	Y.W. Heo	97/2/26
97-16918	Input/ouput pad alignment	D.H. Park	97/5/1
97-16919	CSP semiconductor package using lead on chip	I.T. Han	97/5/1
97-16920	The structure of leadframe	I.T. Han	97/5/1
97-09726	The structure of inner-lead clamp	S.H. Kim	97/5/1
97-09727	Wire-bonding apparatus and spool holder	J.H. Choi	97/5/1
97-18551	Semiconductor package (Attaching heatsink on the top of chip)	W.Y. Pyo	97/5/13
97-18552	Semiconductor package and the method using the same (Eliminating die attaching process)	W.M. Yang	97/5/13
97-18553	Semiconductor package (Positioning closely bending innerlead for heat dissipation)	C.H. Lee	97/5/13
97-18554	The card structure for packaging directly chip	S.G. Lee	97/5/13
97-18555	Semiconductor package (Attaching adhesive tape on heatsink for preventing shorting)	K.J. Kim	97/5/13
97-10616	A tray for storing semiconductor chip	S.M. Seo	97/5/13

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97-10617	A tray for storing semiconductor chip	S.M. Seo	97/5/13
97-10618	A tray for storing semiconductor chip	J.H. Song	97/5/13
97-18506	CSP semiconductor package	S.G. Lee	97/5/13
97-18507	Semiconductor package (Attaching the leadframe of array type at the bottom of package)	S.G. Lee	97/5/13
97-18508	Method and structure recognizing leadframe for wire bonding (Making identification mark at one of the outline leads)	J.W. Park	97/5/13
97-18622	Magazine for semiconductor package	Y.Y. Moon	97/5/13

97-18623	Semiconductor package (Making test terminals in circuit test)	W.S. Shin	97/5/13
97-18624	Semiconductor package (BGA)	W.S. Shin	97/5/13
97-18625	The heater block apparatus of loading leadframe for semiconductor package	S.W. Han	97/5/13
97-18626	Semiconductor package (Attaching heatsink patterned by protrusion shape)	S.K. Lee	97/5/13
97-18627	Semiconductor package and molding device	W.S. Shin	97/5/13
97-18628	Printed circuit board for semiconductor package	Y.M. Kim	97/5/13
97-18629	Semiconductor package (Attaching coupling agent for preventing crack & popcorn from PCB)	W.S. Shin	97/5/13
97-10650	Leadframe for semiconductor package	D.Y. Kim	97/5/13
97-14577	The cleaning apparatus of marking pad	Y.K. Kwak	97/6/17
97-14578	Inspection apparatus and turning structure for manufacturing semiconductor package	Y.K. Kwak	97/6/17

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97-14579	Pushing road apparatus for manufacturing semiconductor package	C.H. Ko	97/6/17
97-14580	Marking apparatus for manufacturing semiconductor package	K.N. Kim	97/6/17
97-14581	The bottom structure of die for manufacturing semiconductor package	K.N. Kim	97/6/17
97-25115	Marking apparatus for manufacturing semiconductor package	H.K. Yang	97/6/17
97-25116	Rotary table apparatus of marking machine for manufacturing semiconductor package	K.N. Kim	97/6/17
97-25117	Input/output magazine apparatus for manufacturing semiconductor package	H.K. Yang	97/6/17
97-25118	Transferring apparatus of marking device for manufacturing semiconductor package	K.H. Kim	97/6/17
97-25119	Turning apparatus of marking device for manufacturing semiconductor package	Y.C. Cho	97/6/17
97-17040	Thermalsetting oven apparatus for semiconductor package	B.H. Moon	97/6/30
97-17041	Trim/form apparatus for manufacturing semiconductor package	J.Y. Ha	97/6/30
97-17042	Tube apparatus for manufacturing semiconductor package	J.Y. Ha	97/6/30
97-29850	Bond-pad structure for semiconductor chip	J.Y. Chung	97/6/30
97-29851	The controlling device of marking apparatus	H.W. Kim	97/6/30
97-31735	A microscope for inspecting wafer	J.H. Choi	97/7/9
97-31960	A cleaning device of semiconductor package	B.S. Bea	97/7/10

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97-32795	Pattern recognition system and recognition method of ground bonding location thereof	W.M. Yang	97/7/15
97-32796	Inner lead clamp construction of wire bonding system for manufacturing semiconductor package and wire bonding method thereof	S.J. Kim	97/7/15
97-26952	Solder ball box of ball bumping system	B.S. Bae	97/6/24
97-30513	The electrode tip mount of the wire-bonding system for semiconductor packages	J.H. Choi	97/7/1
97-31199	The marking head in ink-marking system for semiconductor packages	K.C. Park	97/7/5
97-18255	The heater block of wire-bonder for semiconductor package	S.H. Kim	97/7/10
97-18256	The setting-gauge for capillary in wire bonder	S.H. Kim	97/7/10
97-18257	The wire spool holder of the wire-bonder	S.H. Kim	97/7/10
97-18258	The wire-supply device of the wire-bonder	S.H. Kim	97/7/10

97-32093	Removing method and apparatus for the heat from heater block in the wire bonder	S.H. Kim	97/7/10
97-34517	The solder ball bumping system for BGA semiconductor packages	K.H. Lee	97/7/23
97-34518	The input apparatus of the solder ball bumping system for BGA semiconductor packages	K.H. Lee	97/7/23
97-34519	The pusher of the solder ball bumping system for BGA semiconductor packages	K.H. Lee	97/7/23
97-34520	The flow apparatus of the solder ball bumping system for BGA semiconductor packages	K.H. Lee	97/7/23

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97-34521	The table of ther solder ball bumping system for BGA semiconductor packages	K.H. Lee	97/7/23
97-34522	The material setting apparatus of the solder ball bumping system for BGA semiconductor packages	K.H. Lee	97/7/23
97-34523	The printer of the solder ball bumping system for BGA semiconductor packages	K.H. Lee	97/7/23
97-34524	The solder ball supply apparatus of the solder ball bumping system for BGA semiconductor packages	K.H. Lee	97/7/23
97-34525	The sensing apparatus of double ball in the solder ball bumping system for BGA semiconductor packages	K.H. Lee	97/7/23
97-34526	The solder ball tool of the solder ball bumping system for BGA semiconductor packages	K.H. Lee	97/7/23
97-34527	The PCB-exhauster for solder ball bumping system of BGA semiconductor packages	K.H. Lee	97/7/23
97-19772	Magazine of semiconductor packages	J.Y. Chung	97/7/25
97-18629	Dotted epoxy inspection system of die bonder for manufacturing semiconductor package	J.J. Chun	97/7/15
97-18630	Wire spool construction system for manufacturing semiconductor package	S.H. Kim	97/7/15
97-36487	Pattern recognition system for leadframe and its control method	H.K. Joh	97/7/31
97-39483	The inspection system for BGA semiconductor packages	C.B. Lee	97/8/20
97-39484	The supply device of inspection system for BGA semiconductor packages	S.H. Jang	97/8/20

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97-39485	The griper of inspection system for BGA semiconductor packages	H.D. Lee	97/8/20
97-39486	The material feed device of inspection system for BGA semiconductor packages	S.K. Kim	97/8/20
97-39487	The flow device of inspection system for BGA semiconductor packages	H.H. Park	97/8/20
97-39488	The flow device of inspection system for BGA semiconductor packages	H.H. Park	97/8/20
97-39489	The select device of inspection system for BGA semiconductor packages	H. Cho	97/8/20
97-39490	The material feed tray for BGA semiconductor packages	M.E. Lee	97/8/20
97-22674	Operation system of microscope to wafer inspection	J.H. Choi	97/8/21
97-10103	Method of decreasing bending for integrated circuit package (BGA)	Y.W. Heo	97/3/24 P122847
97-21289	The guide-device of leadframe in trim-form-system for semiconductor packages	K.C. Park	97/8/1
97-25666	The property remove tray of BGA semiconductor package		
97-25668	The property remove tray of BGA semiconductor package	W.J. Kang	97/8/1
97-46504	The mold for semiconductor package	J.C. Hong	97/9/10
97-46505	The heater block of wire-bonding device for semiconductor packages	J.Y. Ha	97/9/10
97-26383	The epoxy application tool of wafer mounting system off	S.H. Kim	97/9/23



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97-26384	The epoxy application tool of wafer mounting system off semiconductor packages	Y.H. Park	97/9/23
97-26385	The wafer table establishment structure of wafer mounting system off semiconductor package	K.B. Choi	97/9/23
97-49085	Cutting device for tie-bar of leadframe	S.J. Oh	97/9/26
97-26791	Structure of a heat slug for semiconductor package	L.H. Kim	97/9/26
97-49241	Structure of a capillary	J.Y. Chung	97/9/26
97-28504	The package cleaning device of ink marking system for BGA semiconductor packages	O.K. Choi	97/10/14
97-52603	Chip ejection method and device for semiconductor packages	D.S. Kim	97/10/23
97-52604	The Top cavity insert structure of mold for semiconductor packages	Y.Y. Moon	97/10/23
97-52605	The mold of semiconductor packages	G.J. Kim	97/10/23
97-52606	Marking method and device of marking system for semiconductor packages	Y.K. Kim	97/10/23
97-52607	Uniformly inking device of marking head in marking system for semiconductor packages	Y.K. Kim	97/10/23
97-52608	The top cavity insert of mold for semiconductor packages	I.S. Kim	97/10/23
97-52609	A Container of wiping fluid for semiconductor packages	Y.J. Han	97/10/23
97-52714	Semiconductor packages	J.Y. Chung	97/10/23
97-54505	Tray for storing ball grid array semiconductor package	S. M. Kim	97/10/23

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97-54506	Tube for storing ball grid array semiconductor package	S. M. Kim	97/10/23
97-54508	Ball grid array semiconductor package using a silicon substrate	W.J. Kang	97/10/23
97-54510	Semiconductor package for a flip chip and its manufacturing method	S.J. Kim	97/10/23
97-54511	Printed circuit board of matrix type	S.J. Kim	97/10/23
97-54512	Flattening method of glob top material surface encapsulated for apparatus	S.W. Shin	97/10/23
97-54513	Metal mold for manufacturing semiconductor package	H.J. Lee	97/10/23
97-54514	Lead frame of semiconductor package	S.G. Lee	97/10/23
97-54515	Marking method of a semiconductor package using a laser beam and its apparatus	S.J. Kim	97/10/23
97-29924	Construction of bond roller for wafer mounter	W.H. Kong	97/10/28
97-29925	Anti-reverse rotation structure of tape roller for wafer mounter	C.B. Lee	97/10/28
97-55636	Wafer mounter having function for attaching barcode label of wafer identification number	W.H. Kim	97/10/28
97-55637	Wafer mounter for semiconductor equipment	W.H. Kong	97/10/28
97-56567	Solder ball array device for ball grid array package	I.S. Kim	97/10/30
97-58067	The epoxy tool of die attach device for semiconductor packages	Y.H. Kim	97/11/4
97-58068	The PCB of BGA semiconductor packages	D.Y. So	97/11/4
97-58069	The Marking test device of semiconductor packages	N.J. Myoung	97/11/4

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97-58070	The Marking test device of PCB for BGA semiconductor packages	J.H. Choi	97/11/4
97-63195	Magazine clamp for semiconductor packages	Y.Y. Moon	97/11/26
97-63196	Wire bonding sensing method and sensing means of wire bonding device for semiconductor packages	J.H. Choi	97/11/26
97-64123	Printed circuit board of wafer taped chip scale package and method of routing it	S.J. Kim	97/11/28
97-64124	Dispensing method of glob top for semiconductor package	W.J. Kang	97/11/28
97-64125	Ball grid array semiconductor package	S.J. Kim	97/11/28
97-64126	The mold of chip array ball grid array package and mold structure using the same	S.J. Kim	97/11/28
97-64127	Printed circuit board of matrix type and molding method of the same	S.J. Kim	97/11/28
97-64128	Mold structure of through gate the for manufacturing semiconductor package and semiconductor package manufacturing method using the same	S.M. Kim	97/11/28
97-65410	Frame for cleaning mold for manufacturing semiconductor package	H.J. Kim	97/12/2
97-72033	Solder ball bumping system for manufacturing semiconductor package	Y.C.Cho	97/12/22
97-72034	Flux dotting device for manufacturing semiconductor package	Y.K. Kwak	97/12/22
97-72035	Solder ball bumping method of semiconductor package and its apparatus	Y.C.Cho	97/12/22

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97-72036	Solder ball mounting method of semiconductor package its apparatus	K.N. Kim	97/12/22
97-43953	Lead frame structure for semiconductor package	S.H. Na	97/12/30
97-43954	Tape automated bonding tool for a semiconductor chip	S.G. Ko	97/12/30
97-43955	Transducer holder for wire bonding of a semiconductor chip	S.G. Ko	97/12/30
97-43956	Magazine structure for safe keeping lead frame	S.M. Hong	97/12/30
97-43957	Blade construction of deflash apparatus for manufacturing semiconductor package	K.C. Park	97/12/24
97-43958	Structure of trim/form device for manufacturing semiconductor package	K.C. Park	97/12/30
97-43959	Mold for manufacturing semiconductor package using a flexible circuit board	S.H. Ha	97/12/30
97-43960	Tube changing device for inserting semiconductor package	H.W. Kim	97/12/30
97-43961	Structure of singulation die for manufacturing semiconductor package	H.W. Kim	97/12/30
97-43962	Capillary for bonding wire of a semiconductor chip	S.G. Ko	97/12/30
97-43963	Mark of tray for semiconductor package	H.W. Cho	97/12/29
97-43964	Manufacturing device for semiconductor package	H.Y. Lee	97/12/30
97-43965	Manufacturing device for semiconductor package	H.Y. Lee	97/12/29
97-43966	Lead frame of semiconductor package	J.H. Cho	97/12/30
97-43967	Paddle structure of lead frame for semiconductor package	S.S. Jang	97/12/30

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97-43968	Paddle structure of lead frame for semiconductor package	S.S. Jang	97/12/30
97-43969	Press system for cutting paddle of lead frame	D.J. Kim	97/12/30
97-79219	Semiconductor package manufacturing method	K.C. Park	97/12/30
97-79220	Deflash method for manufacturing semiconductor package and its apparatus	K.C. Park	97/12/30

97-79221	Inspecting equipment for wire bonding of a semiconductor chip and method thereof	M.S. Shin	97/12/30
97-79222	Structure of chip array ball grid array semiconductor package	J.Y. Yang	97/12/30
97-79223	Automatic ball size filtering device of solder ball bumping system for manufacturing semiconductor package and its method	H.Y. Lee	97/12/30
97-79224	Manufacturing method of semiconductor package	T.B. Jung	97/12/30
97-79225	Ball grid array semiconductor package using a flexible circuit board	S.H. Ha	97/12/30
97-79226	Adhesive layer structure for manufacturing semiconductor package	S.H. Ha	97/12/30
97-79227	Attaching method of flexible circuit board on carrier frame for ball grid array semiconductor units	S.H. Ha	97/12/30
97-79228	Ball grid array semiconductor package using a flexible circuit board	S.H. Ha	97/12/30
97-79229	Solder ball land of ball grid array semiconductor package using a flexible circuit board	S.H. Ha	97/12/30
97-79230	Singulation method of ball grid array semiconductor package using a flexible circuit board strip and its apparatus	S.H. Ha	97/12/30

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97-79231	Wire bonding apparatus for manufacturing semiconductor packages	C.H. Woo	97/12/30
97-79232	Ball grid array semiconductor package using a flexible circuit board and its manufacturing method	S.H. Ha	97/12/30
97-79233	Picker block of ball bumping system for manufacturing semiconductor package	H.Y. Lee	97/12/30
97-79234	Structure of chip size semiconductor package and its manufacturing method	sif, Chowdhury	97/12/30
97-79235	Attaching structure for tube and plug for semiconductor units	J.Y. Ha	97/12/30
97-79236	Marking apparatus for manufacturing a semiconductor package	H.Y. Lee	97/12/30
97-79237	Flux dotting device of ball bumping system for manufacturing semiconductor package	H.Y. Lee	97/12/30
97-79567	Tube -holder for semiconductor packages	J.Y. Ha	97/12/30
97-79572	Manufacturing device of semiconductor packages	G.H. Lee	97/12/30
97-79573	Manufacturing device of semiconductor packages	G.H. Lee	97/12/30
97-79574	Manufacturing device of semiconductor packages	G.H. Lee	97/12/30
97-50557	Plating method for out leads of a semiconductor package	J.W. Lee	97/9/30
98-03920	Lead frame of semiconductor package	M. Yoo	98/3/17
98-03926	Electro flame off tip of wire bonding system for manufacturing semiconductor package	J.Y. Chung	98/3/17
98-09104	Printed circuit board for ball grid array semiconductor package and its manufacturing method		

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98-09105	Blade structure for sawing semiconductor wafer and sawing method using the same	W.S. Lim	98/3/17
98-12364	Semiconductor package	S.G. Lee	98/4/8
98-06790	Tray loading device of semiconductor package manufacturing apparatus	J.I. Oh	98/4/28
98-06791	Ejection device of pick and place system for semiconductor equipment	N.H. Kwak	98/4/28
98-06792	Cassette loading device of mounter system for semiconductor equipment	W.H. Kong	98/4/28
98-06793	Feeding device of material for semiconductor package manufacturing apparatus	N.H. Kwak	98/4/28
98-06794	Magazine fixing device of semiconductor package manufacturing apparatus	W.H. Kong	98/4/28

98-06795	Gripper device for semiconductor package manufacturing apparatus	C.B. Lee	98/4/28
98-06796	Pusher device of semiconductor package manufacturing device	W.H. Kong	98/4/28
98-06797	Dispenser structure of encapsulation apparatus for manufacturing semiconductor	S.B. Na	98/4/28
98-15158	Control method of encapsulation apparatus for manufacturing semiconductor	G.H. Lee	98/4/28
98-15159	Mounter device for semiconductor equipment	C.B. Lee	98/4/28
98-19303	Molding method of printed circuit board for semiconductor package	S. J. Kim	98/5/27

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98-19304	Printed Circuit Board	S. J. Kim	98/5/27
98-09915	Structure of semiconductor package	S.G. Lee	98/6/11
98-09916	Structure of BGA-semiconductor package	S.J. Kim	98/6/11
98-21719	Winding method for end-wire of wire-spool	S.H. Kim	98/6/11
98-21720	Semiconductor package	S.J. Son	98/6/11
98-21721	Structure of semiconductor package	J.Y. Chung	98/6/11
98-23666	BGA-semiconductor packages and its manufacturing method	S.S. Cha	98/6/23
98-12069	Singulation device for manufacturing semiconductor	J.Y. Chung	98/7/2
98-12070	A guide rail structure for semiconductor	Y.Y. Cho	98/7/2
98-12071	Magazine carrier	J.Y. Ha	98/7/2
98-12072	Lead frame of semiconductor package	J.H. Jeong	98/7/2
98-27292	Epoxy resin composition for die attachment	J.S. Kwak	98/7/7
98-35551	Lead frame structure for semiconductor packages	Y.Y. Mun	98/8/31
98-35552	Mold structure for semiconductor packages	Y.Y. Mun	98/8/31
98-35553	Air vent structure of mold for semiconductor packages	Y.Y. Mun	98/8/31
98-35554	Mold structure for semiconductor packages	Y.Y. Mun	98/8/31
98-35555	Manufacturing method and mold structure for F-BGA semiconductor packages	Y.Y. Mun	98/8/31

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98-35604	Wire bonding method for manufacturing semiconductor package	J.H. Yoon	98/8/31
98-35605	Circuit tape for semiconductor package	J.H. Yoon	98/8/31
98-35606	Circuit tape for semiconductor package	J.H. Yoon	98/8/31
98-35607	Circuit tape for semiconductor package	J.H. Yoon	98/8/31
98-35608	Lamination device of wafer and circuit tape for manufacturing semiconductor package and its method	W.H. Kong	98/8/31
98-35609	Attaching device of circuit film and elastomer tape for manufacturing semiconductor package	W.H. Kong	98/8/31
98-35610	Heating and pressure capacity of wafer and circuit tape for manufacturing semiconductor package	N.H. Kwak	98/8/31
98-35611	Cutting device of circuit tape attached to wafer for manufacturing semiconductor package	C.B. Lee	98/8/31
98-35612	Solder ball land structure of film for semiconductor package	J.H. Yoon	98/8/31
98-35613	Circuit tape applied to manufacture of a semiconductor package	J.H. Yoon	98/8/31
98-35614	Manufacturing method of semiconductor package using a circuit tape	J.H. Yoon	98/8/31
98-35615	Circuit tape for semiconductor package	J.H. Yoon	98/8/31
98-35616	Circuit tape for semiconductor package	J.H. Yoon	98/8/31
98-35617	Bonding method of wafer and circuit tape for manufacturing semiconductor package	W.H. Kong	98/8/31
98-35618	Circuit tape and wafer bonding apparatus for manufacturing	W.H. Kong	98/8/31

98-35619	Encapsulation cure method of semiconductor package	J.H. Yoon	98/8/31
98-35620	Marking method for manufacturing semiconductor package	J.H. Yoon	98/8/31
98-35621	Solder ball bumping method for manufacturing semiconductor package	J.H. Yoon	98/8/31
98-35622	Bonding method of wafer and circuit tape for manufacturing semiconductor package	J.H. Yoon	98/8/31
98-35623	Marking method of semiconductor package	J.H. Yoon	98/8/31
98-35624	Manufacturing method of semiconductor package	J.H. Yoon	98/8/31
98-35625	Manufacturing method of semiconductor package	J.H. Yoon	98/8/31
98-36897	Printed circuit board for semiconductor package for preventing static electricity	S.J. Kim	98/9/8
98-36898	Printed circuit board for semiconductor package for preventing static electricity	S.J. Kim	98/9/8
98-37201	Semiconductor device	S.G. Lee	98/9/9
98-37202	Semiconductor device	S.G. Lee	98/9/9
98-37203	Molding device of ball grid array semiconductor using a carrier frame		
98-17327	Method for controlling height of bonding block of did bonder	S.J. Kim	98/9/11
98-17328	Structure dispenser of resin injection apparatus	G.H. Lee	98/9/11
98-17505	Marking device for the lead frame of semiconductor packages	B.S. Chung	98/9/15
98-17506	Inspection jig for the strip of semiconductor packages	S.J. Kim	98/9/15

98-19770	Carrier frame structure for semiconductor packages		
98-19771	Carrier frame structure for semiconductor packages		
98-37969	Lead frame structure of semiconductor packages	Y.H. Choi	98/9/15
98-38052	A method for ascer taining wire bonding state of semiconductor package	C.S. Seo	98/9/15
98-38258	A method for preventing short of bonding wire between bonding pad and lead finger	C.H. Woo	98/9/16
98-38475	Singulation method of ball grid array semiconductor package using flexible circuit board strip	K.W. Lee	98/9/17
98-18090	Semiconductor package	S.H. Ruy	98/9/22
98-39241	Mold structure and method for marking COO mark of semiconductor package using the mold structure	E.H. Pyo	98/9/22
98-40125	Micro ball grid array semiconductor package	J.H. Lee	98/9/26
98-46563	Manufacturing method of circuit board sheet for semiconductor package	Y.G. Park	98/10/31
98-46564	Semiconductor device	I.K. Shim	98/10/31
98-46565	Semiconductor device	I.K. Shim	98/10/31
98-46566	Molding method of semiconductor device	I.K. Shim	98/10/31
98-46567	Manufacturing method of semiconductor package	B.J. Han	98/10/31
98-46568	Semiconductor Package	Y.G. Park	98/10/31
98-46569	Manufacturing method of semiconductor package	B.J. Han	98/10/31

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98-46570	Manufacturing method of semiconductor package	B.J. Han	98/10/31
98-46571	Manufacturing method of semiconductor package	B.J. Han	98/10/31
98-46572	Semiconductor device	I.K. Shim	98/10/31
98-46573	Semiconductor device and its manufacturing method	I.K. Shim	98/10/31
98-46574	Semiconductor package and its manufacturing method	C.K. Park	98/10/31
98-46847	Manufacturing method and device for semiconductor packages	S.H. Kim	98/11/2
98-21474	Equipment for fabricating semiconductor package	S.G. Kim	98/11/5
98-21475	Equipment for fabricating semiconductor package	K.N. Kim	98/11/5
98-21866	Substrate structure for semiconductor packages		
98-47393	Equipment for fabricating semiconductor package	J.H. Yoon	98/11/5
98-47394	Equipment for fabricating semiconductor package	S.B. Na	98/11/5
98-47395	Method for fabricating semiconductor package	K.N. Kim	98/11/5
98-47396	Equipment for fabricating semiconductor package	Y.K. Kwak	98/11/5
98-21568	Substrate for semiconductor packages		
98-21569	Structure of flexibility substrate for semiconductor packages	S.H. Ha	98/11/6
98-47553	Equipment for fabricating semiconductor package	Y.Y. Cho	98/11/6
98-21866	Substrate structure for semiconductor packages	I.G. Han	98/11/11
98-21867	Sawing wheel for wafer cutting	J.Y. Chung	98/11/11

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98-48927	Structure of flexibility substrate for semiconductor packages	D.S. You	98/11/14
98-48928	Semiconductor packages and manufacturing method of it	Chowdhury, Asif	98/11/14
98-48929	Flexible substrate structure and semiconductor packages and manufacturing method with the structure	S.H. Lee	98/11/14
98-49057	Substrate structure and manufacturing for semiconductor packages		
98-49058	Substrate structure and manufacturing method for semiconductor packages	D.H. Park	98/11/16
98-49059	Substrate structure and manufacturing method for semiconductor packages	D.H. Park	98/11/16
98-49060	Strip with display parts and semiconductor packages with the strip	S.S. Cha	98/11/16
98-22488	Structure of flexibility substrate for semiconductor packages	S.H. Ha	98/11/18
98-49887	Semiconductor packages and manufacturing method of it	C.S. Han	98/11/20
98-21618	Semiconductor package manufacturing apparatus	G.H. Lee	98/11/7
98-21619	Semiconductor package manufacturing apparatus	G.H. Lee	98/11/7
98-21620	Semiconductor package manufacturing apparatus	H.D. Lee	98/11/7
98-21621	Semiconductor package manufacturing apparatus	C.H. Ko	98/11/7
98-21622	Semiconductor package manufacturing apparatus	M.H. Park	98/11/7
98-21623	Semiconductor package manufacturing apparatus	S.W. Lee	98/11/7
98-21624	Semiconductor package manufacturing apparatus	C.H. Ko	98/11/7

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98-47878	Method for fabricating semiconductor package	E.H. Pyo	98/11/9
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98-47798	A flexible film for semiconductor packages		
98-48046	Semiconductor package and its manufacturing method	D.H. Park	98/11/10
98-48047	Semiconductor package	B.Y. Min	98/11/10
98-48048	Printed circuit board and manufacturing method of printed circuit board and semiconductor package using the printed circuit board	B.Y. Min	98/11/10
98-49323	Circuit tape for ball grid array semiconductor package		
98-52923	Manufacturing method of semiconductor package	Y.Y. Cho	98/12/3
98-52924	Manufacturing method of semiconductor package	J.H. Lee	98/12/3
98-54095	Method for fabricating semiconductor package	S.H. Lee	98/12/10
98-54999	Wire bonding method of semiconductor device	S.H. Kim	98/12/15
98-25418	Flexible circuit board and semiconductor packages using it	I.G. Han	98/12/17
98-25419	Flexible circuit board structure for semiconductor package	J.E. Hong	98/12/17
98-55910	Semiconductor package	C.H. Woo	98/12/17
98-55911	Semiconductor package and its manufacturing method	S.H. Kim(2)	98/12/17
96-01240	Method of manufacturing chip size semiconductor package	Y.S. Yoon	96/1/22
98-63124	Semiconductor package	E.S. Sohn	98/12/31
98-63125	Semiconductor package	S.H. Lee	98/12/31

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98-63126	Semiconductor package	J.H. Lee	98/12/31
98-63127	Semiconductor package	D.S. You	98/12/31
98-63822	Semiconductor package and its manufacturing method	J.Y. Chung	98/12/31
98-27353	Circuit tape for semiconductor device	J.H. Yoon	98/12/29
98-60454	Manufacturing apparatus of semiconductor device and punching method	J.H. Yoon	98/12/29
98-60456	Wire for semiconductor device	J.S. Kwak	98/12/29
98-62596	Lamination method of semiconductor device and manufacturing apparatus	I.K. Shim	98/12/30
98-62597	Test apparatus of semiconductor package and its test method	Y.C. Cho	98/12/30
98-28225	Wire bonding inspection system for manufacturing semiconductor package	S.H. Jang	98/12/31
98-28226	Inspection apparatus of semiconductor device	G.H. Lee	98/12/31
98-58837	Device for fabricating semiconductor package	S.J. Kim	98/12/26
98-58838	Method for fabricating semiconductor package	S.H. Kim	98/12/26
98-59607	PCB board	S.J. Kim	98/12/28
98-60431	Structure for mold die in fabrication of semiconductor package	D.J. Kim	98/12/29
98-60432	Lead frame and semiconductor package with such lead frame	Y.S. Lee	98/12/29
98-60433	Semiconductor package and method for fabricating the same	I.G. Han	98/12/29
98-27790	Carrier frame for semiconductor packages	D.S. You	98/12/29

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98-27791	Wire bonder capillary	J.Y. Chung	98/12/30
98-27792	Lead frame for semiconductor packages	J.Y. Ha	98/12/30
98-27793	Magazine for semiconductor packages	C.Y. Jang	98/12/30
98-61607	Structure of semiconductor package	D.S. You	98/12/30
98-61608	Structure of semiconductor package	Y.S. Lee	98/12/30
98-61609	A substrate structure and earthing method for semiconductor packages	S.J. Kim	98/12/30

98-61610	Semiconductor packages and manufacturing method of it	T.B. Jung	98/12/30
98-61611	Cull gripper with output transfer arms of auto molding system for semiconductor packages	J.U. An	98/12/30
98-61612	A substrate structure and earthing method for semiconductor packages	S.H. Ha	98/12/30

## Exhibit E, Continued

## II. Japanese Patents and Applications

APPL NO	TITLE	INVENTOR(S)	FILE DATE	PRIORITY	PRIORITY DATE	PATENT NO	ISSUE DATE
6-159039	Mold runner removal from a substrate-based packaged electronic device	Young Wook Heo/ Il Kwon Shim/ Bruce J. Freyman/ John Briar	94-7-11	93-15985	3-08-18		

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6-297411	Method and device for molding of intergrated circuit package (Method)	Goo Lee	96-10-11	93-25829/ 94-22439/ 94-22625	93-11-30/ 94-09-07/ 94-09-07	2742514	98-1-30
6-198341	BGA semiconductor package	Young Wook Heo/ Il Kwon Shim	96-8-25	94-2982	/19/93		
7-153209	Method of reducing delamination between a lead frame and molding compound	Jae Dong Kim	95-6-20	94-5635/ 94-15873	94-03-21/ 94-07-02	2622104	97-4-4
7-148910	Copper-oxide filled polymer die attach adhesive composition for semiconductor package	Choul Woll Kwak	95-6-15	94-13647	4-06-16	2706227	97-10-9
7-153689	Heat spreader suitable for commonly used semiconductor packages having different pad sizes	Myung Jun Lee	95-6-20	94-14028	94-06-21	2592587	96-12-10
7-220236	Semiconductor leadframe having connection bar and guide rings	Won Sun Shin	95-8-29	94-21610/ 94-26326/ 94-25861	94-08-30/ 94-10-10/ 94-10-10	2820645	

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7-241960	Method for checking wire bonding result of BGA package	Young Wook Heo/ Dong Sin Youm	95-9-20	94-24280	94-08-27	2703204	97-10-3
7-345711	Chip mounting plate construction of lead frame for semiconductor package	Youn Cheol Yoo/ Hee Yeoul Yoo/ Jeong Lee/ Doo Hyun Park/ In Gyu Han	95-12-12	94-33994/ 94-37168	4-12-14/ 94-12-27	2767404	4/10/98
7-346366	Semiconductor package with intergral heat dissipator	Won Sun Shin/ Byung Tae Do	95-12-12	94-34663	4-12-16	2660504	97-6-13
7-352582	Ball grid array semiconductor packages with improved heat dissipation and dehumidification effect	Il Kwon Shim/ Young Wook Heo	95-12-28	95-19582	95-07-05	2887144	
7-352583	BGA semiconductor package having exposed heat sink	Il Kwon Shim	95-12-28	95-25172	/16/95	2727435	97-12-12



8-241010	Heat sink-interated semiconductor package with double encapsulating parts and method for fabricating the same	Won Sun Shin	95-8-26	95-28771	5-09-04	Notice of Allowance
8-302542	Printed circuit board having epoxy barrier around a throughout slot and ball grid array semiconductor package	Sun Ho Ha/ Young Wook Heo	96-10-28	95-37513	5-10-27	Notice of Allowance
8-182798	Ball grid array semiconductor package with ring-type heat sink	Il Kwon Shim/ Young Wook Heo	96-6-24	95-41438	5-11-15	2881575
8-320732	Semiconductor package provided with heatsink and surface treating method for such a heat sink	Won Sun Shin/ Won Kyun Lee	96-11-15	95-41844/ 95-44554	5-11-17/ 95-11-29	
8-182799	Unit printed circuit board carrier frame for ball grid array semiconductor package and method for fabricating ball grid array semiconductor packages using the same	Il Kwon Shim/ Young Wook Heo	96-6-24	95-41846	5-11-17	Notice of Allowance

8-243997	Process for bonding semiconductor chip	Seong Min Seo/ Jae Hwan Song	96-8-28	95-42561	5-11-21	2727443	97-12-12
8-354355	Semiconductor chip scale package and method of producing such	Young Wook Heo	96-12-19	95-54765	5-12-12		
8-358683	Semiconductor package lead frame with stress absorbing means on fused leads	Kil Bum Kim/ Young Seok Jung	96-12-27	95-58806	5-12-27	2779789	98-5-15
8-255585	Wafer map conversion method	Chee Jung Song	96-9-5	96-05343	2/29/96		
9-19725	Method of producing BGA semiconductor package metal carrier frame and BGA package produced by such method	Il Kwon Shim/ Young Wook Heo	97-1-17	96-05345	2/29/96	Notice of Allowance	

9-23144	Method of forming chip bumps of bumps chip scale semiconductor package such package and chip bump	Young Wook Heo	97-1-22	96-06302/ 96-06303	6-03-11		
9-98041	Solder Ball land metal structure of ball grid array semiconductor package	Moo Eun Lee	97-3-31	96-09778	6-04-01	2860648	
9-24274	Grid array type lead frame and lead end grid array semiconductor package employing the	Won Sun Shin/ Byung Joon Han/ Ju Hoon Yoon/ Sung Bum Kwak/	97-1-23	96-22897/ 96-22898/ 96-22899	96-06-21		

	same	In Gyu Han				
8-353644	Semiconductor package and method for fabricating the same	Byung Joon Han/ Young Wook Heo	96-12-17	96-22901	96-06-21	2860646
9-275281	Mold for ball grid array semiconductor package	Young Yeop Moon	97-9-22	96-41469/ 70/71/72/ 96-58810/ 11/15/16	6-09-21/ 96-11-28	

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9-289089	Semiconductor package having light, thin simple and compact structure	Seon Goo Lee	97-10-6	96-43843/ 96-46656	96-10-04/96-10-18	
9-304957	Method for reproducing printed circuit boards for semiconductor packages including poor quality printed circuit board units and method for fabricating semiconductor packages using the reproduced printed circuit boards	Sun Ho Ha/ Young Wook Heo/ Byung Joon Han	97-10-20	96-46948	6-10-19	2860651
9-228831	Method for marking poor quality printed circuit board units of printed circuit board strip for semiconductor packages and the printed circuit board strip	Young Wook Heo/ Il Kwon Shim	97-8-11	96-62305	6-12-06	

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9-368681	Alumina-silicon carbide nanocomposite for ball bonding capillaries of wire bonding device and method of manufacturing such	Seok Ho Na	97-12-26	96-77897	6-12-30	
9-233372	Ball grid array semiconductor package with solder balls fused on printed circuit board and method for fabricating the same	Il Kwon Shim/ Young Wook Heo/ Robert Francis Darveaux	97-8-14	96-77898/ 96-77899/ 97-04430	6-12-30/97-02-14	
9-159227	Flexible circuit for ball grid array semiconductor package	Il Kwon Shim/ Young Wook Heo/ Robert Francis Darveaux	97-6-2	96-77900/ 96-77901/ 96-77902	6-12-30	
9-368625	Circuit board with eye-shaped internal circuit tip alignment structure for mounting electronic components	Joong Ho Cho/ Young Seok Chung/ Kyung Sook Choi	97-12-29	96-77919	2/30/96	
10-30663	Method of manufacturing ball grid array semiconductor package	Il Kwon Shim/ Sun Ho Ha	98-1-28	97-02504	/28/97	Notice of Allowance

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10-51459	Circuit board	Sang Suk Cha	98-2-17	97-04656	/17/97
10-58942	Method of fabricating semiconductor package	Young Wook Heo	98-2-24	97-06063	/26/97
10-334667	Method of molding BGA Semiconductor PKG	SungJin Kim	98-11-25	98-19303, 19304, 36897, 36898	98-05-27/98-09-08
10-346145	PCB for grounding BGA Semiconductor PKG	SungJin Kim	98-11-27	97-64125	1/28/97
11-68670	Semiconductor Package	SeonGoo Lee	99-3-15	98-12364	/8/98

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Exhibit E, Continued

### III. United States Patents and Applications

APPL NO	TITLE	INVENTOR(S)	FILE DATE	PRIORITY	PRIORITY DATE	ASSIGNEE
08/349237	Method and device for molding of intergrated circuit package (Device)	Goo Lee	94-10-5	93-25829/ 94-22439/ 94-22625	93-11-30/ 94-09-07/ 94-09-07	Anam & Amkor
08/485936	Copper-oxide filled polymer die attach adhesive composition for semiconductor package	Choul Woll Kwak	95-6-7	94-13647	94-06-16	Anam & Amkor
08/530558	Method for checking wire bonding result of BGA package	Young Wook Heo/ Dong Sin Youm	95-9-19	94-24280	94-08-27	Anam & Amkor
08/588172	Ball grid array semiconductor packages with improved heat dissipation and dehumidification effect	Il Kwon Shim/ Young Wook Heo	96-1-18	95-19582	95-07-05	Anam & Amkor
08/570849	Bonding method for semiconductor	Seong Min Seo/ Sunk Ju Jang	95-12-12	95-28772	95-0904	Anam & Amkor
08/736107	Printed circuit board having epoxy barrier around a throughout slot and ball grid array semiconductor package	Sun Ho Ha/ Young Wook Heo	96-10-24	95-37513	95-10-27	Anam & Amkor
08/749578	Process for bonding semiconductor chip	Seong Min Seo/ Jae Hwan Song	96-11-14	95-42561	95-11-21	Anam & Amkor
08/704477	Wafer map conversion method	Chee Jung Song	96-8-28	96-05343	96-12-29	Anam & Amkor

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08/775839	Grid array type lead frame and lead end grid array semiconductor package employing the same	Won Sun Shin/ Byung Joon Han/ Ju Hoon Yoon/ Sung Bum Kwak/ In Gyu Han	96-12-31	96-22897/ 96-22898/ 96-22899	96-06-21	Anam & Amkor
08/763605	Semiconductor package and method for fabricating the same	Byung Joon Han/ Young Wook Heo	96-12-11	96-22901	96-06-21	Anam & Amkor
09/008552	Semiconductor package and method for fabrication the same	Byung Joon Han/ Young Wook Heo	98-1-16	96-22901	96-06-21	Anam & Amkor
08/915077	Ball grid array semiconductor package with	Il Kwon Shim/ Young Wook Heo/	97-8-20	96-77898/ 96-77899/	96-12-30/ 97-02-14	Anam & Amkor

	solder balls fused on printed circuit board and method for fabricating the same	Robert Frarcis Darveaux		97-04430		
08/883541	Flexible circuit for ball grid array semiconductor package	Il Kwon Shim/ Young Wook Heo/ Robert Frarcis Darveaux	97-6-25	96-77900/ 96-77901/ 96-77902	96-12-30	Anam & Amkor
09/013330	Method of manufacturing ball grid array semiconductor package	Il Kwon Shim/ Sun Ho Ha/ Robert Frarcis Darveaux	98-1-26	97-02504	1/28/97	Anam & Amkor
09/024940	Method of fabricating semiconductor package	Young Wook Heo	98-2-17	97-06063	2/26/97	Anam & Amkor

EXECUTION COPY

## TRANSITION SERVICE AGREEMENT

This Transition Service Agreement ("Agreement") is made and entered into this 6th day of May, 1999 by and between and Amkor Technology Korea, Inc., a corporation organized under the laws of the Republic of Korea ("ATK"), and Anam Semiconductor, Inc., a corporation organized under the laws of the Republic of Korea ("Anam").

## W I T N E S S E T H:

WHEREAS, Anam and Amkor Technology, Inc. ("ATI") have entered into a certain Asset Purchase Agreement dated as of December 30, 1998 (the "Asset Purchase Agreement") and an amendment to the Asset Purchase Agreement dated May 3, 1999 (the "Amendment"), pursuant to which ATK and ATI will purchase and acquire from Anam the assets in K4; and

WHEREAS, in order to support the continued and uninterrupted operation of K4 from the time of Closing, the parties to the Asset Purchase Agreement and the Amendment agreed to enter into an arrangement whereby Anam will continue to provide to ATK certain of its services that have been provided by Anam to K4 prior to the Closing Date, in accordance with the terms and conditions of this Agreement and Section 4.7 of the Asset Purchase Agreement.

NOW, THEREFORE, in consideration of the mutual covenants, agreements and obligations set forth herein, the parties hereto agree as follows:

ARTICLE I  
DEFINITIONS

Section 1.1. Definitions. Unless otherwise defined in this Agreement, all of the capitalized terms used in this Agreement shall have the same meanings as they are defined in the Asset Purchase Agreement.

ARTICLE II  
TERM

Section 2.1. Term. The term of this Agreement shall commence on the Closing Date of the Asset Purchase Agreement (the "Effective Date") and shall continue until the parties to this Agreement separately agree, unless terminated on an earlier date pursuant to Article 7 of this Agreement.

ARTICLE III  
THE SERVICES

Section 3.1. Services to be provided by Anam. During the term of this Agreement, Anam shall provide to ATK all of the services and parts and components currently provided to the Business by Anam including, among other things, the research and development, accounting, data processing, materials procurement, electronic data processing, administrative services and all other such support services as are reasonably required in connection with the operation of the Business as described in detail in the Schedules attached to

this Agreement (collectively, "Services" and, individually, "Service"), upon the detailed terms and at the rates specified in such Schedules.

### Section 3.2 Services to be Provided.

(a) Anam shall ensure that the Business is continued to be provided with all of the Services, on the terms and conditions not less favorable than the terms and conditions pursuant to which such services and parts and components are now being provided to the Business.

(b) In addition to the Services, Anam shall ensure that all services currently made available to the employees of the Business including, without limitation, cafeteria, clinic and human welfare services continue to be provided to the Transferred Employees on the same terms and conditions as such services which have been provided to them.

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### Section 3.3. Specifics and Costs of Services.

(a) The attached Schedules of Services and costs are subject to change with the parties' mutual written consent. The parties hereto shall use good faith efforts to discuss any change of charge for a Service; provided, however, that any occurrence of events and change of circumstances shall not justify stopping a provision of Services by Anam under this Agreement.

(b) ATK is contracting for use of Anam's system on an "as-is" basis. After the Closing Date, if there will be any modifications to Anam's systems at ATK's request, Anam will make its best efforts to implement such modifications at an actual cost basis.

(c) If there will be a separation of system at ATK's discretion for the implementation of ATK's own independent systems, Anam agrees to cooperate as reasonably requested by ATK in order to effectuate such separation.

Section 3.4. Additional Services. In addition to the Services, the parties hereto acknowledge that there may be additional services and facilities which have not been identified herein but which have been used by K4 prior to the Closing Date and which shall continue to be required or desired by ATK until the termination of this Agreement, or such later date as the parties may agree upon. If any such additional services or facilities are identified and requested by ATK, and Anam agrees to provide such services, ATK will be charged at a rate to be agreed by Anam and ATK.

## ARTICLE IV PAYMENT AND INVOICE

### Section 4.1. Service Fees.

(a) The fees payable by ATK to Anam for the Services shall be as set forth in Schedules (the "Service Fees").

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Notwithstanding anything to the contrary contained herein, ATK shall not be charged under this Agreement for any Service that is specifically required to be performed under any other agreement between Anam and ATK and any such other Service shall be performed and charged for in accordance with the terms of such other agreement.

(b) In the event that a Service commences, expires or terminates

on any day other than the first day of a calendar month, the applicable Service Fee shall be calculated on a pro rata basis based on the actual number of days during which the Service was provided and a month of 30 days.

#### Section 4.2. Payment.

(a) Anam shall invoice ATK monthly in arrears within fifteen (15) calendar days of the end of the month in question in relation to an amount payable for the Services provided to ATK during such month. ATK shall pay an amount invoiced by Anam and any sales, value-added or similar taxes on any amounts to be paid to Anam hereunder in full within thirty (30) calendar days of the date of receipt of Anam's invoice.

(b) Other than the Service Fees, no cost or expense, including any out-of-pocket expense paid to a third party by Anam as result of Services provided hereunder by Anam to ATK, shall be charged separately to ATK.

### ARTICLE V WARRANTIES

Section 5.1. Express Warranties. Anam warrants that the Services under this Agreement shall be of substantially the same type and quality as have been provided for the benefit of K4 prior to the Effective Date, and shall be of such type and quality as are reasonably required to appropriately operate K4 in a commercially reasonable manner.

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### ARTICLE VI INDEMNITY; LIMITATION OF LIABILITY

Section 6.1. Indemnity. Anam shall indemnify and hold harmless ATK from and against any loss, demand, liability, claim, cost or expense of whatever kind (collectively, "Damages") arising from and incurred by ATK due to the negligence or willful misconduct of Anam or its personnel assigned for the Services under this Agreement.

Section 6.2 Survival. The provisions of this Article VI shall survive the termination of this Agreement.

### ARTICLE VII TERMINATION

#### Section 7.1. Termination.

(a) This Agreement may be terminated with respect to all or a portion of the Services at any time as follows:

- (i) by mutual written agreement of the parties;
- (ii) at the written election of one party, in the event of a material default by the other party of its obligations hereunder, which default shall not have been cured within sixty (60) calendar days after written notice given by the non-defaulting party to the defaulting party; or
- (iii) at the written election of one party, in accordance with Section 8.1(d).

(b) ATK may terminate any Service(s) provided pursuant to this Agreement on ninety (90) days prior written notice to Anam, unless otherwise specified in Schedules. If ATK elects to terminate a Service, it will bear the costs of interfacing any new

system to the remaining Anam systems which it continues to use. ATK shall no longer be obligated to pay Anam the Service Fees attributable to such canceled Service(s) following the effective termination date of such Service(s) provided that ATK fully pays any and all Service Fees, charges or other similar payment due and accrued in connection with Service(s) provided up to and including the effective termination date.

(c) No termination of this Agreement (including any early termination of a Service pursuant to paragraph (b) above) shall discharge, affect or otherwise modify in any manner the rights and obligations of the parties hereto which have accrued or have been incurred prior to such termination, including, without limitation, the obligation of ATK to pay Anam any and all amounts payable hereunder for, or related to, the Services theretofore provided.

#### ARTICLE VIII FORCE MAJEURE

##### Section 8.1. Force Majeure.

(a) A party is not liable for a failure to perform any of its obligations under this Agreement insofar as it proves that the failure was due to an impediment beyond its reasonable control.

(b) An impediment within paragraph (A) above may result from events including, but not limited to, (i) war, whether declared or not, riots, acts of sabotage, explosions, fires, destruction of equipment/machines, or inability to obtain raw materials, (ii) natural disasters, such as violent storms, earthquakes, floods and destruction by lightning, (iii) the intervention of any Governmental Authority, and (iv) boycotts, strikes and lock-outs of all kinds and work-stoppages.

(c) A party seeking relief hereunder shall as soon as practicable after the impediment and its effects upon its ability

to perform became known to it give notice to the other party of such impediment.

(d) If the grounds for relief subsist for [ninety (90)] days or more, either party shall be entitled to terminate this Agreement with written notice to the other party pursuant to Article 5.

#### ARTICLE IX MISCELLANEOUS

Section 9.1. Notices. All notices, reports and other written communications permitted or required to be delivered by the provisions of this Agreement shall be delivered to the party due to receive such notice, report, or other written communication personally, by facsimile or by air courier service at the relevant address set out below or such other address as the party may specify by notice to the other:

to Anam: Anam Semiconductor, Inc.  
280-2, 2-ga, Sungsu-dong  
Sungdong-gu, Seoul 133-706 Korea  
Attn: K.H. Kim



to ATK: Amkor Technology Korea, Inc.  
Advanced Science & Industrial Complex, 2 block  
Daechon-dong, Buk-gu, Kwangju 500-470 Korea  
Attn: Michael D. O'Brien

Section 9.2. Governing Law and Jurisdiction. This Agreement and the terms and conditions hereof shall be governed by and construed and interpreted in accordance with the laws of the Republic of Korea. Any and all disputes which may not be amicably settled by the parties shall be subject to the non-exclusive jurisdiction of the Seoul District Court, and Anam and ATK each hereby agree and consent to be subject to the jurisdiction of such court.

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Section 9.3. Effectiveness. The parties' obligations under this Agreement are conditioned upon the Closing, the occurrence of which is subject to various conditions set forth in the Asset Purchase Agreement. This Agreement shall become operative if and when the Closing occurs and shall be null and void if this Closing does not occur for any reason.

Section 9.4. Headings. The headings in this Agreement are inserted for convenience only and are in no way intended to describe, interpret, define or limit the scope, extent or intent of this Agreement or any provisions hereof.

Section 9.5. Amendment; Waiver. Any provision of this Agreement may be amended or waived if, and only if, such amendment or waiver is in writing and signed, in the case of an amendment, by Anam and ATK, or in the case of a waiver, by the party against whom the waiver is to be effective. No failure or delay by any party in exercising any right, power or privilege hereunder shall operate as a waiver thereof nor shall any single or partial exercise thereof preclude any other or further exercise thereof or the exercise of any other right, power or privilege.

Section 9.6. Severability. If any provision of this Agreement or the application thereof to any person or circumstance shall be deemed invalid, illegal or unenforceable to any extent or for any reason, such provision shall be severed from this Agreement and the remainder of this Agreement and the application thereof shall not be affected and shall be enforceable to the fullest extent permitted by law. A provision which is valid, legal and enforceable shall be substituted for the severed provision.

Section 9.7. Parties in Interest. This Agreement shall inure to the benefit of and be binding upon the parties and their respective successors and permitted assigns. Nothing in this Agreement, express or implied, is intended to confer upon any Person other than Anam or ATK, or their successors or permitted assigns, any rights or remedies under or by reason of this Agreement.

Section 9.8. Counterparts. This Agreement may be executed in one or more counterparts, each of which shall be deemed an original, and all of which shall constitute one and the same agreement.

Section 9.9. Entire Agreement. This Agreement, the Asset

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Purchase Agreement and the other agreements referred to in the Asset Purchase Agreement contain the entire agreement between the parties hereto with respect to the subject matter hereof and supersede all prior agreements and understandings, oral or written, with respect to such matter.

Section 9.10. Relationship of the Parties. Anam shall perform all Services hereunder as an independent contractor. This Agreement does not create a fiduciary or agency relationship between Anam and ATK, each of which shall be and at all times remain independent companies for all purposes hereunder. Nothing in this Agreement is intended to make either party a general or special agent, joint venturer, partner or employee of the other for any purpose.

Section 9.11. Assignment. Neither party to this Agreement may assign any of its rights or obligations under this Agreement, without the prior written consent of the other party hereto.

Section 9.12. Fulfillment of Obligations. Any obligation of any party to any other party under this Agreement, which obligation is performed, satisfied or fulfilled by an Affiliate of such party, shall be deemed to have been performed, satisfied or fulfilled by such party.

Section 9.13. Public Announcement. Prior to the Closing, neither Anam nor ATK shall, without the approval of the other party hereto, make any press release or other public announcement concerning the terms of the transactions contemplated by this Agreement, except as may be required to comply with requirements of any applicable Laws, and the rules and regulations of any stock exchange upon which the securities of one of the parties is listed, in which case the party shall use its Best Efforts to advise the other party thereof and the parties shall use their Best Efforts to cause a mutually agreeable release or announcement to be issued; provided that the foregoing shall not preclude communications or disclosures necessary to implement the provisions of this Agreement.

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IN WITNESS WHEREOF, the parties have caused this Agreement to be duly executed in counterparts the day and year first written above.

ANAM SEMICONDUCTOR, INC.

By: /s/  
-----

Name: -----

Title: -----

AMKOR TECHNOLOGY KOREA, INC.

By: /s/  
-----

Name: -----

Title: -----

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## Schedule A

### PLANNING SERVICES

#### A. Contents of Services

This Service includes budget and investment control, performance evaluation, projection of annual business plan, collection of data & information, government & public relations. Details of the services that will be provided to ATK are as follows:

- Provide a guide line for investment and budget, including review of the feasibility of proposed investments;
- Provide annual business plan, which involves the following year's P&L projection, investments plan, resources, and related matters;
- Collect and provide an internal and external data and information, including the data and information regarding yield rate, cost, turnover rate, investment status, semiconductor market overview, new package trend, customer related information, etc;
- Provide services relating government relation; and
- Provide company related news and advertisement to the public whenever it is necessary.

#### B. Service Fee

Fee to be paid by ATK per month shall be US\$40,250 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 7 employees of Anam out of 24 employees working for planning service are exclusively assigned for the service to ATK.

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## Schedule B

### SPECIAL CUSTOMER SERVICES

#### A. Contents of Service

This Service is for the biggest customer of ATK, Intel. The services includes quality improvement of Intel products, cost reduction follow-up, critical part inventory, maintain direct communication with Intel, and all related matters.

#### B. Service Fee

Fee to be paid by ATK per month shall be US\$6,417 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 3 employees of Anam out of 7 employees working for special customer service are exclusively assigned for the service to ATK.

## Schedule C

## GENERAL AFFAIRS (GA) SERVICES

## A. Contents of Service

This Service includes company security, employees benefits, document control, overseas business trip control, information desk, fixed asset control, sub-contractor control, company transportation control, printing house, broadcasting, and related matters. Details of the services that will be provided for ATK are as follows:

- Manage fixed assets including allocation of equipment, liquidation of equipment, establishment and maintenance of asset management control system, etc;
- Coordinate contracts for outsourcing;
- Establish strategy for operating vehicles, cafeteria, etc;
- Support and manage employees' overseas trip such as reservation of air ticket and hotel, travel expenses, etc; and
- Provide printing service using printing house in K1.

## B. Service Fee

Fee to be paid by ATK per month shall be US\$29,000 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 8 employees of Anam out of 153 employees working for general affairs service are exclusively assigned for the service to ATK.

## Schedule D

## HUMAN RESOURCE DEVELOPMENT SERVICES

## A. Contents of Service

This Service includes hiring and retirement, allocation of employees, performance rating, promotion of employee, training and education of employee, company regulation, and rewarding and punishment of employees. Details of the services are as follows:

- [Hire operators independently;]
- [Evaluate performance of employees in connection with promotion and reward & punishment of employees;] and
- Establish company regulations.

Training for the employees hired for the operation of K4 shall be done independently by ATK at its own costs.

## B. Service Fee

Fee to be paid by ATK per month shall be US\$80,083 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 18 employees of Anam out of 90 employees working for human resource development service are exclusively assigned for the service to ATK.

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#### Schedule E

##### EMPLOYEE-RELATED SERVICES

###### A. Contents of Service

This Service includes labor strategy, employee benefits, company outdoor program, employee health program, payroll & social security payment and other labor-related matters. Details of the services which will be provided to ATK are as follows:

- Provide advice to the management of employees;
- Manage funds for the employee benefit, decide the types and value of the gifts and bonuses to be given to the employees; and
- Manage employee payrolls, severance pay and the social security payments.

###### B. Service Fee

Fee to be paid by ATK per month shall be US\$8,333 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 4 employees of Anam out of 25 employees working for employee related service are exclusively assigned for the service to ATK.

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#### Schedule F

##### FINANCE & ACCOUNTING SERVICES

###### A. Contents of Service

This Service will include following:

- Manage funds;
- Provide foreign exchange service relating to export and import;
- Prepare accounting books and records for monthly closing;
- Manage tax payment; and
- Manage receipts and disbursements.

###### B. Service Fee

Fee to be paid by ATK per month shall be US\$133,083 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 9

employees of Anam out of 30 employees working for financing and accounting services are exclusively assigned for the services to ATK.

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#### Schedule G

##### EXPORT & IMPORT IN LOGISTICS

###### A. Contents of Service

This Service will include following:

- Support custom related services when imported materials are transferred to ATK;
- Select and contract with forwarders for exporting and importing;
- Provide custom clearance and other government related services;
- Prepare record of exporting and importing performances; and
- Manage Anam Trade Information Service Tracking System at K4.

###### B. Service Fee

Fee to be paid by ATK per month shall be US\$9,833 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 3 employees of Anam out of 14 employees working for financing and accounting services are exclusively assigned for the services to ATK.

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#### Schedule H

##### MATERIAL CONTROL

###### A. Contents of Service

This Service will include following:

- Die input and labeling;
- Die receiving and inspection;
- Manage die flow;
- Manage material inventory and bill-back services; and
- Manage carrying in/out of other materials and spare parts.

###### B. Service Fee

Fee to be paid by ATK per month shall be US\$9,670 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 4 employees of Anam out of 74 employees working for material control service are exclusively assigned for the service to ATK.

Schedule I  
PURCHASING SERVICES

A. Contents of Service

This Service will include following:

- \_ Establish purchasing strategy;
- \_ Market trend analysis (PCB, L/F, Equipment, etc);
- \_ Price negotiation (PCB, L/F, Equipment, etc);
- \_ Select supplier;
- \_ Follow-up monitoring (Delivery, Quality, Inventory, etc); and
- \_ Manage purchasing system

B. Service Fee

Fee to be paid by ATK per month shall be US\$16,830 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 8 employees of Anam out of 27 employees working for purchasing service are exclusively assigned for the service to ATK.

Schedule J  
R&D SERVICES

A. Contents of Service

This Service will include following:

- \_ Manages Technology Information Management System;
- \_ Produce technology engineering report, and hold technology related seminars;
- \_ Develop new package design and run simulations
- \_ Develop direct/indirect material and support suppliers of ATK;
- \_ Support K4 plant for its new package line-up; and
- \_ License relevant patent to ATK;

B. Service Fee

Fee to be paid by ATK per month shall be US\$63,083 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 24 employees of Anam out of 102 employees working for R&D service are

exclusively assigned for the service to ATK.

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#### Schedule K

##### QA SUPPORTING SERVICES

###### A. Contents of Service

This Service includes will include following:

- \_ Material and Die incoming quality assurance;
- \_ Conduct an audit for suppliers;
- \_ Conduct reliability test for the finished goods; and
- \_ Quality related specification and document control.

###### B. Service Fee

Fee to be paid by ATK per month shall be US\$32,920 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 16 employees of Anam out of 80 employees working for QA supporting service are exclusively assigned for the service to ATK.

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#### Schedule L

##### CUSTOMER SERVICES

###### A. Contents of Service

This Service includes direct communication with customer and providing data that customer has requested. Details of the services are as follows:

- \_ Customer resident support;
- \_ Sales support (billing service, new customer service representative training, etc);
- \_ Manufacturing monitoring (On-time delivery monitoring, emergency lot control, hand-carry service, etc); and
- \_ Follow-up "Voice of Customer"

###### B. Service Fee

Fee to be paid by ATK per month shall be US\$23,250 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 15 employees of Anam out of 63 employees working for customer service are exclusively assigned for the service to ATK.



## Schedule M

## SALES &amp; MARKETING SERVICES

## A. Contents of Service

This Service is for sales and marketing in both domestic and Japan customers. Details of the services are as follows:

- \_ Contract with domestic and Japan customer;
- \_ Produce forecast for the customer;
- \_ Manage delivery time and cost of products;
- \_ Analyze market trend and package trend; and
- \_ Maintain good relationships with customers.

## B. Service Fee

Fee to be paid by ATK per month shall be US\$17,583 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 7 employees of Anam out of 23 employees working for sales and marketing service are exclusively assigned for the service to ATK.

## Schedule N

## PRODUCTION PLANNING SERVICES

## A. Contents of Service

This Service includes the following:

- \_ Produce overall production volume forecasts and conduct performance control;
- \_ Produce summary sheets of manpower and equipment efficiency;
- \_ Control capacity and material usage;
- \_ Control plant lay-out;
- \_ Support expatriates support (housing, vehicles, tax, etc);
- \_ Conduct cost control:
  - ABC (Activity Based Costing)
  - Produce cost modeling
  - Generate line cost and P&L by PKG, plant, company
  - Calculate and analyze average sales price; and
- \_ Select equipment and demonstration of new equipment
- \_ Manage overall "Suggestion Program";
- \_ Manage and support ATK's "Small Group Activity" and "Improvement Team Activities";

- Improve working environment and minimize loss or rejection in production line;
  - Manage the Product Data Base; and
  - Enter orders (pin count updates, registration of a new package)
- B. Service Fee

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Fee to be paid by ATK per month shall be US\$37,830 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 11 employees of Anam out of 33 employees working for production planning service are exclusively assigned for the service to ATK.

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#### Schedule O

##### ICS SERVICES

###### A. Contents of Service

This Service includes the following:

- Develop all the information and technology programs for the plant;
- Develop and establish inter-company networking system- Notes System (e-mail, information sharing system);
- Select hardware (PC, Server, Video conference equipment, etc) and maintain the hardware;
- Select software for the office users; and
- Maintain telecommunications system.

###### B. Service Fee

Fee to be paid by ATK per month shall be US\$182,417 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 15 employees of Anam out of 51 employees working for ICS service are exclusively assigned for the service to ATK.

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#### Schedule P

##### MANAGEMENT ASSISTANCE SERVICES

###### A. Contents of Service

This Service includes the following:

- Provide financial management, including overall management of financial matters, including contacts with the creditor banks and development of the financial policies.
- Coordinate public relations with public media, such as newspapers, magazines and broadcasting companies, publication of monthly corporate magazine for Anam's and ATK's employees and coordination of CI ("Corporate Identity") project.
- Provide support for the senior management of Anam and ATK.
- Provide construction, environment and safety management services in connection with the management of environment and construction of K4.

B. Service Fee

Fee to be paid by ATK per month shall be US\$60,916 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 15 employees of Anam out of 46 employees working for management support service are exclusively assigned for the service to ATK.

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Schedule Q

SECRETARIAL SUPPORT

A. Contents of Service

This Service includes the following:

- Provide secretarial support for the senior management of Anam and ATK, including the Chairman of Anam.
- Provide assistance and coordination services among Anam, Anam USA and ATI.

B. Service Fee

Fee to be paid by ATK per month shall be US\$27,666 (exclusive of any VAT) which has been agreed by the parties, on the assumption that 4 employees of Anam out of 12 employees working for secretarial support are exclusively assigned for the service to ATK.

## Exhibit 23.1

## CONSENT OF INDEPENDENT PUBLIC ACCOUNTANTS

We hereby consent to the inclusion of this Current Report on Form 8-K of Amkor Technology, Inc. (the "Company") of our report dated February 10, 1999 except for Note 4 as to which the date is March 18, 1999 (the "Report"), which contains explanatory paragraphs on the Kwangju Packaging Business' dependence on support from Amkor Technology Inc., the Kwangju Packaging Business' operations affected by unstable economy in Asia Pacific region and "Workout Program" of Anam Semiconductor Inc. on our audits of the carved out financial statements of the Kwangju Packaging Business of Anam Semiconductor Inc. We also hereby consent to the incorporation of our Report included in this Form 8-K into the Company's previously filed Registration Statement on Form S-8 (No. 333-62891).

SAMIL ACCOUNTING CORPORATION

May 28, 1999  
Seoul, Korea

AMKOR TECHNOLOGY

NEWS RELEASE

Contact: Jeffrey Luth  
VP Investor Relations  
Amkor Technology, Inc.  
ext. 5613

AMKOR TECHNOLOGY COMPLETES ACQUISITION OF K4 PACKAGING PLANT  
AMKOR NOW OWNS PREMIER SEMICONDUCTOR PACKAGING COMPLEX

West Chester, PA - May 17, 1999 - Amkor Technology, Inc. (Nasdaq:AMKR) said today that it has completed the acquisition of the K4 semiconductor packaging plant from Anam Semiconductor, Inc. for approximately \$582 million, including the assumption of \$7 million in employee benefit liabilities. The transaction was funded with the proceeds of Amkor's recently completed offering of \$625 million in long term debt.

With more than 1,000,000 square feet of total facility space, and nearly 800,000 square feet of manufacturing / administrative space, K4 is one of the world's largest semiconductor packaging plants. Located on a 100-acre site in Kwangju, South Korea, K4 has the infrastructure already in place to accommodate an additional 1.6 million square feet of manufacturing space when fully expanded.

"Amkor's ownership of this world class facility has important strategic benefits," said Amkor's President, John Boruch. "Often referred to as a city-in-a-city, K4 is a state-of-the-art, fully expandable complex that assembles some of the most technologically advanced semiconductor devices in the world, including many of our advanced leadframe and laminate package products. According to industry analysts, the market for laminate package products is projected to experience significant growth over the next several years due to the ongoing miniaturization of semiconductor design and increasing integration of functions within a package. We expect Amkor to be a significant participant in that market growth as it develops," added Mr. Boruch.

"K4's existing physical plant, together with its fully-expandable configuration, provides Amkor with the capability to accommodate the rapidly growing needs of the marketplace for advanced semiconductor packaging products," continued Mr. Boruch. "We are delighted to welcome the more than 1700 highly trained employees of K4 into the Amkor family."

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"With the acquisition of K4, Amkor now owns and operates four packaging and test factories, including three in the Philippines," noted Mr. Boruch. "While we will continue to subcontract a sizable portion of our packaging and test business under a long-term supply agreement with Anam Semiconductor, the acquisition of K4 puts more of our revenue within our wholly owned factories. As production volume at K4 continues to ramp, we expect to increase our manufacturing margins, since the gross margin on K4-derived revenue will no longer be subject to the contractual limitations of the supply agreement."

"While we are incurring considerable interest expense with this acquisition, K4 is expected to be a substantial contributor to Amkor's EBITDA during 1999," continued Mr. Boruch.

Amkor's Executive Vice President, Michael D. O'Brien, will have overall

responsibility for Amkor Technology Korea. Dan Sparks joins Amkor Technology Korea as Director of Finance. Mr. Sparks will be based in Kwangju and will be responsible for managing the development of financial accounting and reporting systems at K4.

The K4 facility opened in 1996 and commenced volume production in 1997. K4 has been building manufacturing volume throughout 1997 and 1998, during which time several of the world's leading semiconductor companies have qualified K4 for package production. Amkor expects to accelerate the ramp up of production at K4 during the next 12 to 24 months to meet projected market requirements.

Amkor Technology, Inc. is the world's largest provider of contract semiconductor packaging and test services. The company offers a complete set of semiconductor services including deep submicron wafer fabrication, wafer probe testing, IC packaging assembly and design, final testing, burn-in, characterization and reliability testing. More information on Amkor Technology, Inc. is available from the company's SEC filings and on Amkor's web site, <http://www.amkor.com>. Amkor is traded on the Nasdaq Stock Market under the symbol AMKR.

The statements in this news release may contain forward-looking statements - such as (1) the belief that the market for laminate products is expected to experience significant growth over the next several years; (2) the expectation that Amkor will be a significant participant in the market growth for laminate products; (3) the expectation that Amkor will increase manufacturing margins at K4; (4) the expectation that K4 will be a significant contributor to Amkor's EBITDA during 1999; and (5) we will accelerate the ramp up of production at K4 during the next 12 to 24 months - that involve risks and uncertainties that could cause actual results to differ from anticipated results. Further information on risk factors that could affect the company's results is detailed in the company's filings with the Securities and Exchange Commission, including the Report on Form 10-K for the fiscal year ended December 31, 1998.

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